

FORM PTO-1390
(REV. 11-2000)

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

TRANSMITTAL LETTER TO THE UNITED STATES
DESIGNATED/ELECTED OFFICE (DO/EO/US)
CONCERNING A FILING UNDER 35 U.S.C. 371

ATTORNEY'S DOCKET NUMBER

3132

U.S. APPLICATION NO. (If known, see 37 CFR 1.5)

097787638

INTERNATIONAL APPLICATION NO.

PCT/EP99/07534

INTERNATIONAL FILING DATE

7 October 1999

PRIORITY DATE CLAIMED

7 October 1998

TITLE OF INVENTION

METHOD FOR PRODUCING A MICROTRANSPONDER

APPLICANT(S) FOR DO/EO/US

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Applicant herewith submits to the United States Designated/Elected Office (DO/EO/US) the following items and other information:

1. ☒ This is a **FIRST** submission of items concerning a filing under 35 U.S.C. 371.
2. ☐ This is a **SECOND** or **SUBSEQUENT** submission of items concerning a filing under 35 U.S.C. 371.
3. ☒ This is an express request to begin national examination procedures (35 U.S.C. 371(f)). The submission must include items (5), (6), (9) and (21) indicated below.
4. ☒ The US has been elected by the expiration of 19 months from the priority date (Article 31).
5. ☒ A copy of the International Application as filed (35 U.S.C. 371(c)(2))
 - a. ☒ is attached hereto (required only if not communicated by the International Bureau).
 - b. ☐ has been communicated by the International Bureau.
 - c. ☐ is not required, as the application was filed in the United States Receiving Office (RO/US).
6. ☒ An English language translation of the International Application as filed (35 U.S.C. 371(c)(2)).
 - a. ☒ is attached hereto.
 - b. ☐ has been previously submitted under 35 U.S.C. 154(d)(4).
7. ☒ Amendments to the claims of the International Application under PCT Article 19 (35 U.S.C. 371(c)(3))
 - a. ☐ are attached hereto (required only if not communicated by the International Bureau).
 - b. ☐ have been communicated by the International Bureau.
 - c. ☐ have not been made; however, the time limit for making such amendments has NOT expired.
 - d. ☐ have not been made and will not be made.
8. ☐ An English language translation of the amendments to the claims under PCT Article 19 (35 U.S.C. 371 (c)(3)).
9. ☐ An oath or declaration of the inventor(s) (35 U.S.C. 371(c)(4)).
10. ☐ An English language translation of the annexes of the International Preliminary Examination Report under PCT Article 36 (35 U.S.C. 371(c)(5)).

Items 11 to 20 below concern document(s) or information included:

11. ☒ An Information Disclosure Statement under 37 CFR 1.97 and 1.98.
12. ☐ An assignment document for recording. A separate cover sheet in compliance with 37 CFR 3.28 and 3.31 is included.
13. ☒ A FIRST preliminary amendment.
14. ☐ A SECOND or SUBSEQUENT preliminary amendment.
15. ☒ A substitute specification.
16. ☐ A change of power of attorney and/or address letter.
17. ☐ A computer-readable form of the sequence listing in accordance with PCT Rule 13ter.2 and 35 U.S.C. 1.821 - 1.825.
18. ☐ A second copy of the published international application under 35 U.S.C. 154(d)(4).
19. ☐ A second copy of the English language translation of the international application under 35 U.S.C. 154(d)(4).
20. ☐ Other items or information:

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
PATENT OPERATIONS**

Art Unit: (Examiner)

Applicant(s): Andreas PLETTNER and Karl HABERGER

Serial No:

Filed:

Title: METHOD FOR PRODUCING A MICROTRANSPONDER

Charlotte, North Carolina
March 19, 2001

Honorable Commissioner of Patents
Washington, DC 20231

Dear Sir:

PRELIMINARY AMENDMENT

Preliminary to Examination of the above-identified application, kindly amend the application as follows:

In the Specification:

Please substitute the attached specification for the translation of PCT Application PCT/EP99/07534 filed on October 7, 1999, with the European Patent Office.

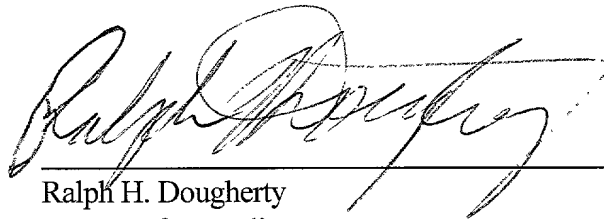
In the Claims:

Please substitute the attached claims for those included in the translation of PCT Application PCT/EP99/07534 filed on October 7, 1998, with the European Patent Office.

REMARKS

Entry of the Amendment substituting the attached substitute specification and claims is respectfully requested by Applicants.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Ralph H. Dougherty", is written over a horizontal line.

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Docket 3132

704-366-6642

09/787638
JC02 Rec'd PCT/PTO 20 MAR 2001

National Phase of PCT/EP99/07534 in U.S.A.

Title: Method for Producing a Microtransponder

Applicants: Andreas PLETTNER; Karl HABERGER

Final version of PCT/EP99/07534 for the prosecution at the
USPTO to be filed as first preliminary amendment

6/8/75

Method for Producing a Microtransponder

BACKGROUND OF THE INVENTION

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Field of the Invention

The present invention relates to a method for producing a microtransponder, especially a microtransponder of the type
10 having a circuit chip which contains the transponder electronics, and having in addition a coil metallization which acts as an antenna.

15 Description of Prior Art

Due to the development of contact-bearing and contactless chip cards, a completely new and rapidly growing market for electronic microsystems has come into existence. Integrated
20 circuits are nowadays installed not only in large devices or manually held systems, but they are installed so to speak "naked" in chip cards. A consistent further development leads to the so-called "throw-away electronics", the first representative of which was the telephone card. More recent fields
25 of use for this so-called "throw-away electronics" are electronic labels which necessitate economy-priced chips or micromodules in economy-priced, ecologically acceptable supports. The simplest case of an electronic label would be a contactless module embedded between two pieces of paper, the
30 contact module comprising an integrated circuit and an antenna coil.

Transponder modules for electronic labels are disclosed in the Patent Abstracts of Japan, publication number 09297535A, relating to the Japanese application 08109052 and the Patent Abstracts of Japan, publication number 09293130A relating to
5 the Japanese application 08109051. In the case of the electronic labels described in the above-mentioned publications an integrated circuit chip together with an antenna are cast in a film-like resin. This film-like resin is then introduced into a metal mould where an outer resin is cast around the
10 film-like resin.

The Patent Abstracts of Japan, publication number 090198481A, relating to Japanese application 08005845 disclose an electronic label in the case of which a circuit chip and a loop-
15 type antenna are applied to a substrate, the outer end of the antenna being connected to a terminal on the integrated circuit via a bridging metallization which is conducted over the windings of the antenna and which is separated from these windings by means of an insulating resin layer.

20 The Patents Abstracts of Japan, publication No. 08216573A, relating to Japanese application 07021785 describes a contactless IC card comprising a circuit chip and an antenna section. The circuit chip is attached to a circuit section
25 provided on a polyester film, the antenna section being formed on this polyester film as well. By means of an adhesive layer, a second polyester film, which embeds the circuit chip, is formed on the first polyester film. In addition, a third polyester film is applied to the surface of the second
30 polyester film by means of a further adhesive layer.

In DE 19639902 A1 contactless chip cards and methods of producing the same are described. The chip cards described in

this publication comprise an electrically insulating, one-piece card body having one or a plurality of openings on one side thereof. Furthermore, a conductor pattern is provided on the surface of the card body, the conductors being directly
5 applied to surface areas of the card body side provided with at least one opening, and the openings having arranged therein one or a plurality of chips which are bonded to at least one of the conductors.

10 A survey of known methods of applying integrated circuit chips to a substrate, e.g. by means of a flip-chip method, is contained in H. Reichl, et al: Packaging-Trends: "High-Tech im Kleinstformat", Elektronik 12/1998 (or SMT Nürnberg 98, Conference Proceedings).

15

SUMMARY OF THE INVENTION

It is the object of the present invention to provide an economy-priced method, which permits the production of ultraflat
20 microtransponders that are suitable to be used e.g. for electronic labels.

This object is achieved by a method for producing a micro-
25 transponder in the case of which an antenna metallization having a first and a second connecting end is first applied to a support substrate. Furthermore, a connecting metallization is applied to a flexible support foil, whereupon a circuit chip having a first and a second connecting area is applied
30 to the connecting metallization in such a way that at least the first connecting area of the circuit chip is connected to the connecting metallization in an electrically conductive manner. The support substrate and the support foil

are then joined in such a way that the connecting metallization is connected to the first connecting end of the antenna metallization in an electrically conductive manner and the second connecting area of the circuit chip is connected to the second connecting end of the antenna metallization in an electrically conductive manner. Edge areas of the flexible support foil are then joined to neighbouring areas of the support substrate so as to encapsulate at least the circuit chip.

10

It follows that the present invention provides a method for producing a microtransponder in the case of which two modules are initially formed, which are joined in the last step. The first module comprises a support substrate, which may consist e.g. of plastic material or of paper and on which the antenna metallization, i.e. the coil, is formed. The second module comprises a thin support substrate, which consists preferably of plastic material, and which has applied thereto one or more connecting metallizations and the circuit chip. These two modules are then joined in such a way that the contacts required for the electric connections between the coil and the circuit chip are realized. The support foil is then used for encapsulating the circuit chip and optional further areas of the coil metallization and of the connecting metallizations, respectively, by joining edge areas of the support foil with neighbouring areas of the support substrate by means of welding or by means of an adhesive so that especially the circuit chip can be protected against external influences.

30

According to the present invention, the two modules can first be processed separately from one another so that one module can be processed without taking into consideration the re-

spective other module. The two modules can then be joined in such a way that, when they are being joined, all the necessary electric connections will be established. Through-contacts through the support substrate, which are only re-
5 quired in the case of some embodiments, have to be established in a separate step before or after the joining of the two modules. When the two modules have been joined, the thin support foil, which, on the one hand, serves to handle the circuit chip and the connecting metallization, is used in ac-
10 cordance with the present invention for encapsulating at least the circuit chip and preferably also the areas in which the connections between the connecting metallization and the antenna metallization are realized, by joining edge areas of this thin support foil to the support substrate by means of
15 welding or by means of an adhesive. This encapsulation is carried out preferably in a vacuum or making use of a protective gas so as to prevent an inclusion of possibly detrimental substances.

20 Embodiments and further developments of the present invention are defined in the dependent claims.

BRIEF DESCRIPTION OF THE DRAWINGS

25 In the following, preferred embodiments of the present invention will be explained in detail making reference to the drawings enclosed, in which respective identical elements are designated by identical reference numerals.

30 Fig. 1a) to 1e) show a schematic representation for illustrating a first embodiment of the method according to the present invention;

Fig. 2a) to 2d) show a schematic representation for illustrating a second embodiment of the method according to the present invention;

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Fig. 3a) to 3e) show a schematic representation for illustrating a third embodiment of the method according to the present invention;

10 Fig. 4a) to 4e) show a schematic representation for illustrating a fourth embodiment of the method according to the present invention;

15 Fig. 5a) to 5e) show a schematic representation for illustrating a fifth embodiment of the method according to the present invention;

20 Fig. 6a) to 6c) show a schematic representation for illustrating a sixth embodiment of the method according to the present invention;

25 Fig. 7a) to 7c) show a schematic representation for illustrating a seventh embodiment of the method according to the present invention.

DESCRIPTION OF PREFERRED EMBODIMENTS OF THE INVENTION

30 Making reference to Fig. 1, the first embodiment of the method according to the present invention will now be explained in detail. As has been stated above, two separate modules are first produced in the case of the method for producing a microtransponder according to the present invention.

The first module produced is shown in Fig. 1a). In the case of this embodiment, a first connecting metallization 2 and a second connecting metallization 4 are first applied to a thin support foil 6, which consists preferably of plastic material, so as to produce this first module, which can also be referred to as circuit chip module. Subsequently, a circuit chip 8 is applied to the connecting metallizations 2 and 4. The circuit chip 8 comprises the integrated circuit required for the microtransponder and is provided with two connecting areas on or in one main surface thereof; for operating the microtransponder, these connecting areas must be connected to respective connecting ends of a coil antenna metallization. The circuit chip 8 is applied to the connecting metallization 2 in such a way that the first connecting area thereof is connected to the first connecting metallization 2 in an electrically conductive manner, whereas the second connecting area thereof is connected to the connecting metallization 4 in an electrically conductive manner. This results in the structural design of the first module shown in Fig. 1a).

This first module is produced from extremely thin materials. This is important in view of the fact that, when the microtransponder has been finished, the circuit chip 8 with the support foil 6 should not perceptibly project beyond a support substrate on which the coil metallization is arranged. The circuit chip and the foil preferably have a thickness of less than 50 μm .

The connecting metallizations 2 and 4, which may consist e.g. of Al, Cu and the like, can be applied to the foil by arbitrary methods, e.g. by cladding and subsequent structuring, by evaporation or sputtering and subsequent structuring, or alternatively by evaporation or sputtering making use of a

shadow mask so as to apply lines which are already structured. The connecting metallizations may have a thickness of less than 1 μm , since the conductor tracks of the connecting metallizations can be implemented such that they are short and broad. When the connecting metallizations 2 and 4 have been finished, the circuit chip 8 is placed on the contact areas of the connecting metallizations and is connected thereto in an electrically conductive manner; this can be done e.g. by means of thermocompression, anisotropic conductive adhesives or ultrasonic compression.

In Fig. 1b) the second module is shown, which comprises a support substrate 10 and an antenna metallization 12 applied to a main surface of the support substrate 10. The support substrate may consist e.g. of plastic material or paper. The antenna metallization 12, which has the form of a coil, can again be formed on the support substrate 10 by arbitrary known methods. The coil metallization can e.g. be formed by etching a cladding. Alternatively, a wire can be placed onto the support substrate 10 such that a coil is formed. According to another alternative, a metal, e.g. Cu, Al and the like, can be applied to the support substrate 10 by evaporation and structured subsequently. In order to obtain an adequate thickness of the coil metallization 12 the evaporated metallization can subsequently be thickened by means of an electroplating technique. As can additionally be seen in Fig. 1b), a local thin insulating layer 14 is produced, e.g. by means of a printing process, in an area of the coil metallization 12. This local insulating layer is produced in an area onto which the second connecting metallization 4 will be placed later on so as to prevent a short circuit between the second connecting metallization 4 and the coil metallization 12.

At this point reference should be made to the fact that, alternatively to the application of the insulating layer 14 to the coil metallization 12, this local insulating layer may also be formed on corresponding areas of the first module, e.g. by means of a suitable printing process or by surface oxidation of the metallization. Since the lines of the first module are very thin in comparison with the antenna metallization, which may have a thickness of e.g. 4 to 30 μm , it may be more advantageous to form the insulating layer on the first module, which is shown in Fig. 1a). The insulating layer 14 can consist of an acrylic lacquer having a thickness of 0.2 to 2 μm , this acrylic lacquer being then locally removed at the future contact points; this is done by means of a thermal process. If the local insulating layer is formed on the first module, this can be done prior to or subsequent to the application of the circuit chip 8 to the connecting metallizations 2 and 4.

The first module and the second module are now joined in a subsequent step, as shown in Fig. 1c). In so doing, the first connecting metallization 2 is connected to a first connecting end 16 of the antenna metallization 12 in an electrically conductive manner, whereas the second connecting metallization 4 is connected to a second connecting end 18 of the antenna metallization in an electrically conductive manner. In the embodiment shown in Fig. 1, an isoplanar contact is obtained in this way. As can be seen in Fig. 1d), the support foil 6 is then connected along its edges to the support substrate 10 in such a way that, in the embodiment shown, the circuit chip 8 as well as the connecting areas between the antenna metallization and the connecting metallization are encapsulated. This can be achieved by bending the edges of

the thin support foil 6 towards the support substrate 10 and by subsequently joining the foil areas 20 abutting on the support substrate 10 to the support substrate 10 by means of welding or by means of an adhesive, as can be seen in Fig. 1d). It follows that, according to the present invention, an encapsulation of the circuit chip and, in the case of the embodiment shown, of the connection points can be accomplished in a simple manner so as to provide protection against external influences. This connection process between the support foil 6 and the support substrate 10 is preferably carried out in a vacuum.

A top view of the microtransponder produced by means of the above method is shown in Fig. 1e). In this top view, especially the shape of the connecting metallizations 2 and 4 and the arrangement of the insulating layer 14 can be seen.

Fig. 2 shows a schematic representation of a second embodiment of the production method according to the present invention. The method shown in Fig. 2 corresponds essentially to the method described with reference to Fig. 1, the support substrate 10 having, however, provided therein an opening/recess 30 into which the circuit chip 8 is introduced when the first and second modules are being joined. The opening 30 can be formed in the support substrate 10 by means of arbitrary known methods. Since the support foil 6 and the thin connecting metallization 2 provided thereon are flexible, the shape of the support foil 6 shown at 32 in Fig. 2c) is obtained. One advantage of this embodiment of the method according to the present invention is that the opening 30 permits an improved protection of the circuit chip 8 and that, in addition, the circuit chip can be fixed more effectively. The edge areas of the support foil 6 are again joined

to neighbouring areas of the support substrate 10 by means of an adhesive or by means of welding so as to achieve an encapsulation of the circuit chip.

5 In Fig. 3 a third embodiment of the method according to the present invention is schematically shown. In Fig. 3a) the second module is shown, which corresponds to the above-described second module. In Fig. 3b) the first module is shown, which also corresponds to the above-described first
10 module. Other than in the case of the above-described embodiments, the first and the second module are now, however, joined in such a way that the circuit chip 8 will be positioned on the surface of the support substrate 10 which is located opposite the surface of the support substrate 10 hav-
15 ing the antenna metallization 12 formed thereon, cf. Fig. 3c). It follows that in the third embodiment shown, an electrically conductive connection between the first and second connecting ends of the antenna metallization 12 and the first and second connecting metallizations 2 and 4 is not yet es-
20 tablished simultaneously with the joining of the first and second modules. In order to realize this electrically conductive connection, through-contacts 40 and 42, respectively, are established, cf. Fig. 3d). By means of the through-
25 contact 42 an electrically conductive connection is established between the first connecting metallization 2 and the first connecting end 16 of the antenna metallization 12, whereas by means of the through-contact 40 an electrically conductive connection is established between the second connecting metallization 4 and the second connecting end 18 of
30 the antenna metallization 12.

In order to establish the through-contacts, thermocompression methods can be used by way of example. Alternatively, the

through-contacts can be produced by means of an ultrasonic compression, by means of welding or by means of soldering. In this respect, it should be pointed out that the through-contacts may already be produced when the two modules have not yet been joined, i.e. in the stage of the second module which is shown in Fig. 3a), so that, when the two modules are being joined, the respective electrically conductive connections between the through-contacts and the connecting metallizations will be produced. As can be seen in Fig. 3e), the edge areas 20 of the support foil are again joined to neighbouring areas of the support substrate 10 by means of welding or by means of an adhesive, so as to encapsulate the circuit chip and, in the embodiment shown, additional areas.

The fourth embodiment of the method according to the present invention shown in Fig. 4 differs from the embodiment which has been described with respect to Fig. 3 insofar as the surface of the support substrate 10 located opposite the antenna metallization 12 has formed therein an opening 50 into which the circuit chip 8 is introduced when the first and second modules are being joined. As can be seen in Fig. 4c, this permits an isoplanarity of the connecting metallizations 2 and 4. As in the case of the embodiment according to Fig. 3, through-contacts 40, 42 are again produced for establishing an electrically conductive connection between the connecting metallizations 2 and 4 and the first and second connecting ends 16 and 18 of the antenna metallization 12. Furthermore, also according to the fourth embodiment, the edge areas 20 of the support foil 6 are joined to neighbouring areas of the support substrate 10 by means of welding or by means of an adhesive so as to effect an encapsulation.

In the case of the method shown in Fig. 5, a circuit chip 60 is used, which is provided with a first connecting area on a first main surface thereof and with a second connecting area on a second main surface thereof. The first module shown in
5 Fig. 5a) is now formed by applying a single connecting metallization 62 to a support foil 6. The circuit chip 60 is applied to the connecting metallization 62, an electrically conductive connection being established between the connecting area of the circuit chip 60 and the connecting metalliza-
10 tion 62 e.g. by means of conductive adhesives or by means of soldering.

Fig. 5b) shows the second module; for producing this second module, an antenna metallization 64 is first applied to a
15 support substrate 10. As can be seen in Fig. 5b), the antenna metallization 64 has a preferably enlarged second connecting end 66, the circuit chip 60, whose lower surface may be provided with a metallization 68 thickening the connecting area, being applied to this second connecting end 66 when the first
20 and second modules are being joined. As has already been explained with reference to Fig. 1, a local insulating layer 70 is formed on respective areas of the antenna metallization 64 also in the case of the embodiment shown in Fig. 5 so as to prevent later on a short circuit between the connecting met-
25 allization 62 and the antenna metallization 64.

The first module is now connected to the second module, cf. Fig. 5c), a contact between the metallization 68, i.e. the second connecting area on the lower surface of the circuit
30 chip 60, and the second connecting end of the antenna metallization 66 being established simultaneously, and an electrically conductive connection between the connecting metallization 62 and the first connecting end 72 of the antenna metal-

lization 64 being established simultaneously. As can be seen in the detail representations shown in Fig. 5d), the edge areas 20 of the support foil 6 are connected, i.e. joined by means of welding or by means of an adhesive, to corresponding
5 neighbouring areas of the support substrate 10 also in the case of this embodiment. Fig. 5e) shows a top view of the resultant microtransponder.

In the sixth embodiment of the method according to the present invention, which is schematically shown in Fig. 6, a
10 first module is again prepared, which essentially corresponds to the first module shown in Fig. 5. This first module is shown in Fig. 6b). The second module differs from the module described with reference to Fig. 5 insofar as an opening
15 80 is formed in the main surface of the support substrate 10 facing away from the antenna metallization 64, Fig. 6a). As can be seen in Fig. 6c), the circuit chip 60 is introduced in this opening 80 when the two modules according to this embodiment are being joined. For establishing an electric con-
20 tact between the connecting area, or the reinforcement 68, arranged on the upper surface of the circuit chip and the second connecting end 66 of the antenna metallization 64, it is necessary to eliminate, preferably by means of a thermally supported method, the web 82 of the support substrate ar-
25 ranged above the opening 80, so as to establish an electrically conductive connection between the connecting area arranged on the upper surface of the circuit chip 60 and the second connecting end 66 of the antenna metallization 64. Furthermore, a through-contact 84 is produced so as to estab-
30 lish an electrically conductive connection between the connecting metallization 62 and the first connecting end 72 of the antenna metallization 64. Also in the case of this embodiment, the edges of the support foil 6 are joined to the

support substrate 10 by means of welding or by means of an adhesive so as to obtain an encapsulation.

Also in the embodiment which is schematically shown in Fig. 7, a circuit chip 60 with double-sided contacting is used. Other than in the case of the method described with reference to Fig. 6, the support substrate 10 has now provided therein an opening 90 which extends through the whole support substrate 10 up to the second connecting end 66 of the coil metallization 64. The rest of the method for producing the microtransponder according to the embodiment shown in Fig. 7 corresponds essentially to the method which has been described with reference to Fig. 6, but the heat treatment for eliminating a web above the opening 90 can now be dispensed with, since such a web does not exist. The other steps correspond to the steps which have been described with reference to Fig. 6.

It should be pointed out that the second connecting end 66 of the antenna metallization 64 may cover the circuit chip 60 completely or partially. Furthermore, the metallization 68 on the circuit chip 60 may cover the circuit chip completely or partially; a person skilled in the art will also be aware of the fact that, with the exception of the connecting area of the circuit chip 60, a passivation layer is arranged between the metallization 68 and the circuit chip 60.

It follows that the present invention provides a simple technique for producing a microtransponder in the case of which the production of the antenna module and the production of the circuit chip module are completely separated. The circuit chip module can be implemented such that it is much thinner than the antenna module. Various production techniques can be

used for producing the antenna module and for producing the circuit chip module. Due to the fact that the circuit chip is encapsulated or that large areas thereof are covered by a metallization, good light protection can be achieved. The methods according to the present invention are preferably executed such that the individual modules are formed on an endless material and are then sequentially supplied to a processing station in which the modules are joined. The respective metallic layers may consist of a ferromagnetic material so as to permit, if necessary, magnetic handling of the individual modules or of the finished microtransponder. For handling the thin circuit chip module, the circuit chip module may be supported by an additional support so as to stabilize it, whereby distortions or even rolling up due to internal mechanical stress can be avoided. The encapsulation of the circuit chip and of additional optional areas is preferably carried out in a vacuum or while a protective gas, e.g. a forming gas, is being supplied.

What is claimed is:

1. A method for producing a microtransponder comprising the
5 following steps:

applying an antenna metallization having a first and a
second connecting end to a support substrate;

- 10 applying a connecting metallization to a flexible support
foil;

- a) applying a circuit chip having a first and a second
connecting area to said connecting metallization in
15 such a way that at least the first connecting area of
the circuit chip is connected to the connecting metal-
lization in an electrically conductive manner;

- b) joining the support substrate and the support foil in
20 such a way that the connecting metallization is con-
nected to the first connecting end of the antenna met-
allization in an electrically conductive manner, and
that the second connecting area of the circuit chip is
connected to the second connecting end of the antenna
25 metallization in an electrically conductive manner; and

- c) joining edge areas of the flexible support foil to
neighbouring areas of the support substrate so as to
encapsulate at least the circuit chip.

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2. A method according to claim 1, wherein the edge areas of
the flexible support foil are welded to the neighbouring
areas of the support substrate.

3. A method according to claim 1, wherein the edge areas of the flexible support foil are joined to the neighbouring areas of the support substrate by means of an adhesive.

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4. A method according to claim 1, wherein in step b) a first and a second connecting metallization are applied to the flexible support foil, and wherein in step c) the circuit chip, which is provided with said first and second connecting areas on a first main surface thereof, is applied to said first and said second connecting metallizations in such a way that the first connecting area is connected to the first connecting metallization in an electrically conductive manner and the second connecting area is connected to the second connecting metallization in an electrically conductive manner, the second connecting area being, in step d), connected via the second connecting metallization to the second connecting end of the antenna metallization in electrically conductive manner.

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5. A method according to claim 1, wherein the circuit chip applied in step c) has the first connecting area on a first main surface thereof and the second connecting area on a second main surface thereof, which is located opposite said first main surface.

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6. A method according to claim 4, wherein in step d) the support foil and the support substrate are joined in such a way that the antenna metallization and the circuit chip are arranged on the same main surface of the support substrate.

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7. A method according to claim 4, wherein the circuit chip is introduced in step d) in an opening in the support-substrate main surface to which the antenna metallization has been applied.
- 5
8. A method according to claim 6, wherein an insulator structure is provided so as to insulate the second connecting metallization from the antenna metallization with the exception of the location at the second connecting
- 10 end of the antenna metallization.
9. A method according to claim 4, wherein the support foil and the support substrate are joined in step d) in such a way that the antenna metallization and the circuit chip
- 15 are arranged on opposed main surfaces of the support substrate, the first and second connecting metallizations being connected by means of through-contacts to the first and second connecting ends of the antenna metallization.
- 20 10. A method according to claim 4, wherein in step d) the circuit chip is introduced in an opening provided in the main surface of the support substrate which is located opposite the main surface having the antenna metallization applied thereto, the first and second connecting
- 25 metallizations being connected by means of through-contacts to the first and second connecting ends of the antenna metallization.
- 30 11. A method according to claim 5, wherein the support foil and the support substrate are joined in step d) in such a way that the antenna metallization and the circuit chip are arranged on the same main surface of the support substrate.

- 12.A method according to claim 5, wherein in step d) the circuit chip is introduced into an opening provided in the main surface of the support substrate which is located opposite the main surface having the antenna metallization applied thereto, the connecting metallization being connected via a through-contact to the first connecting end of the antenna metallization.
- 10 13.A method according to claim 1, wherein step e) is executed in a vacuum or making use of a protective gas.

ABSTRACT

5 According to a method for producing a microtransponder, an antenna metallization having a first and a second connecting end is first applied to a support substrate so as to form a first module. A connecting metallization is applied to a flexible support foil, whereupon a circuit chip having a
10 first and a second connecting area is applied to said connecting metallization in such a way that at least the first connecting area of the circuit chip is connected to said connecting metallization in an electrically conductive manner. The flexible support foil having the circuit chip applied
15 thereto represents a second module. The first and the second module are subsequently joined in such a way that the connecting metallization is connected to the first connecting end of the antenna metallization in an electrically conductive manner and the second connecting area of the circuit
20 chip is connected to the second connecting end of the antenna metallization in an electrically conductive manner. Finally, edge areas of the flexible support foil are joined to neighbouring areas of the support substrate so as to encapsulate at least the circuit chip.

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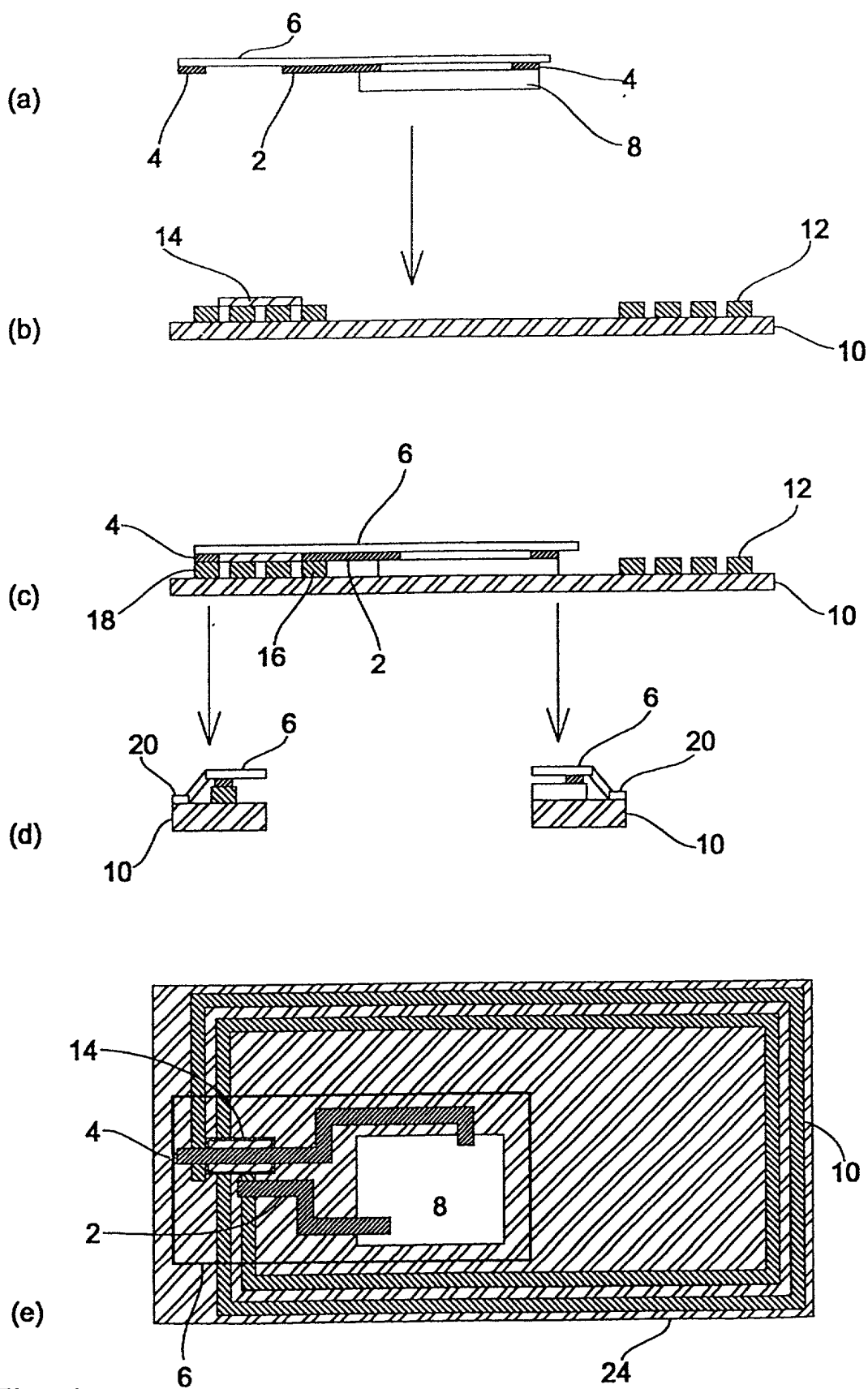


Fig. 1

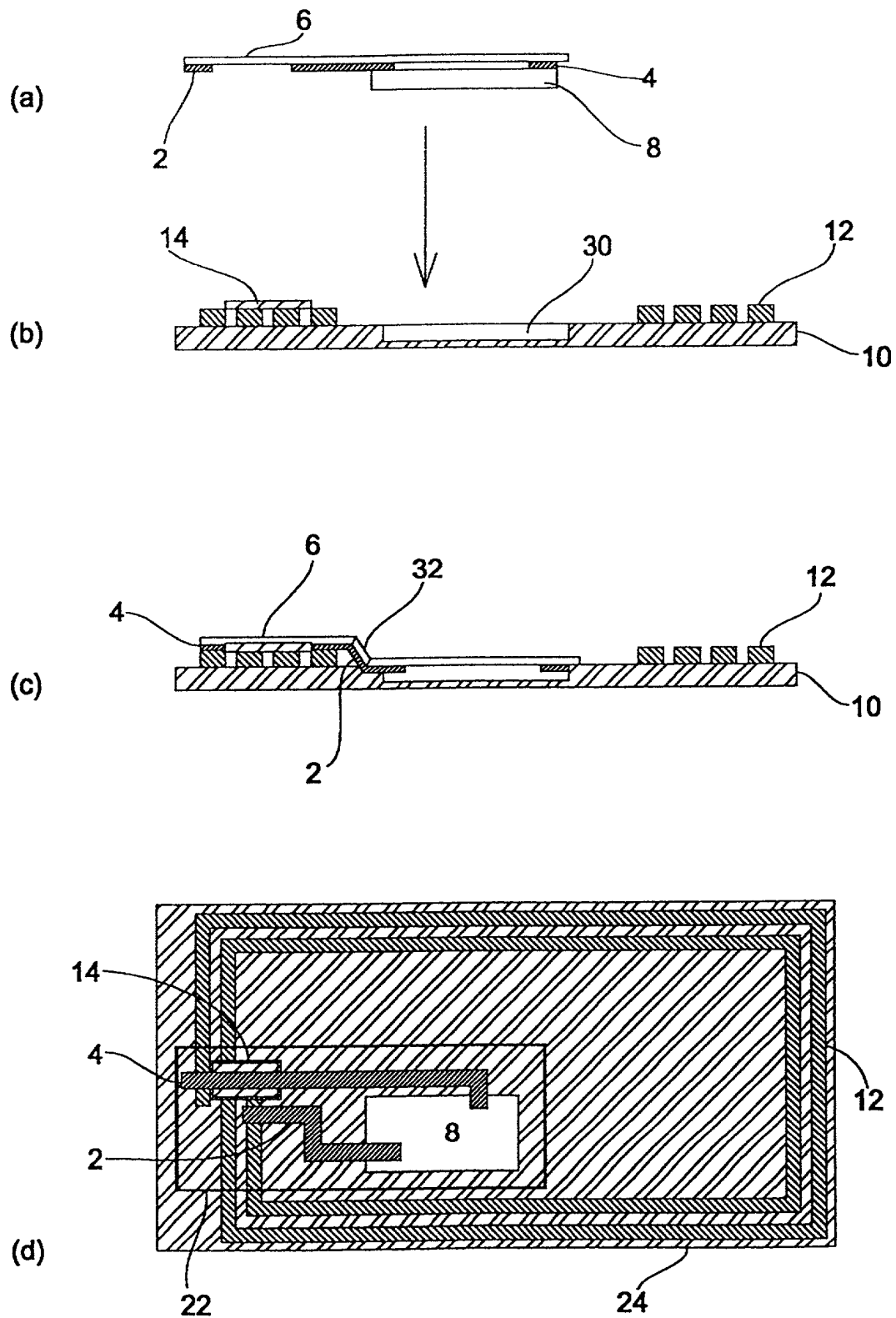


Fig. 2

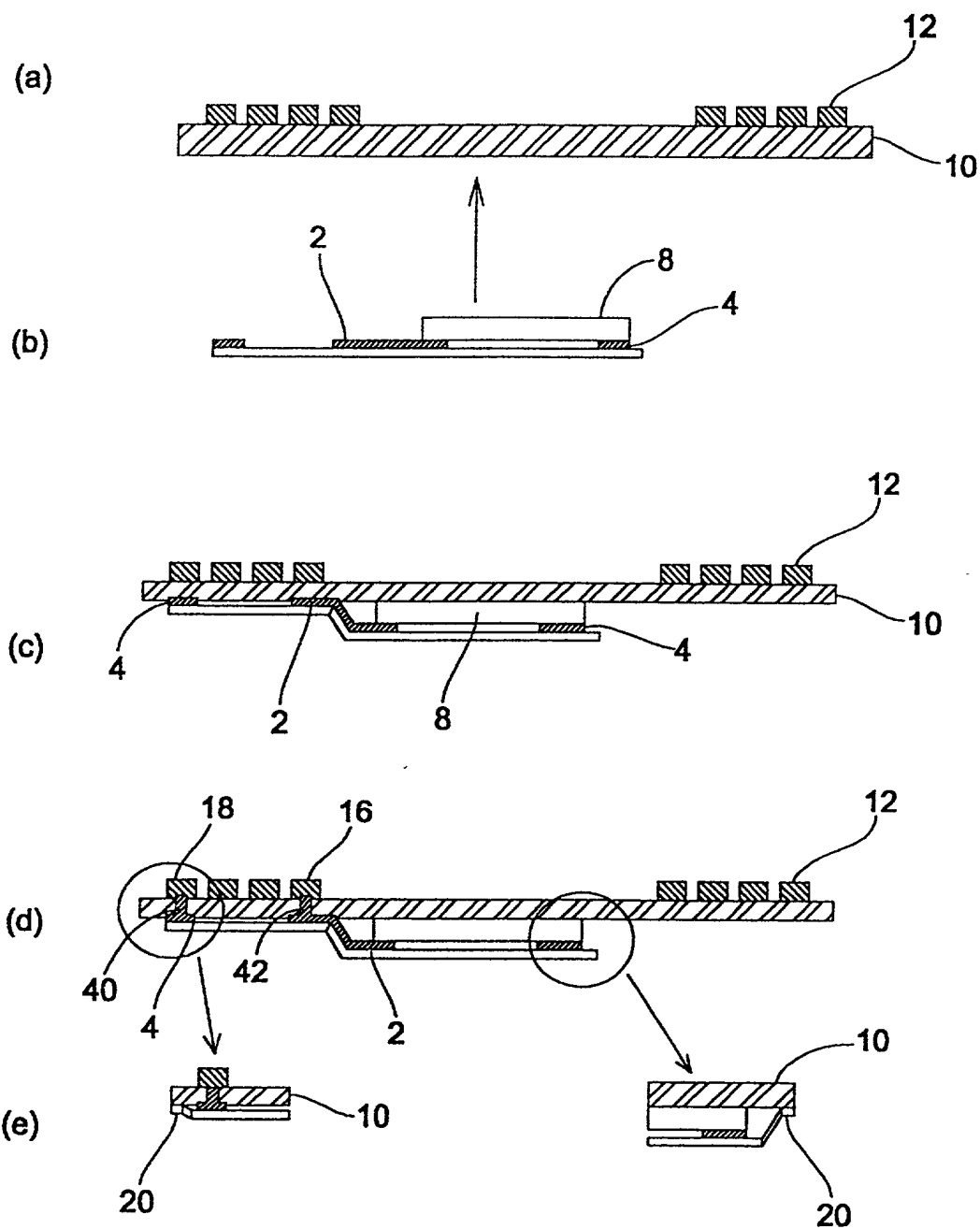


Fig. 3

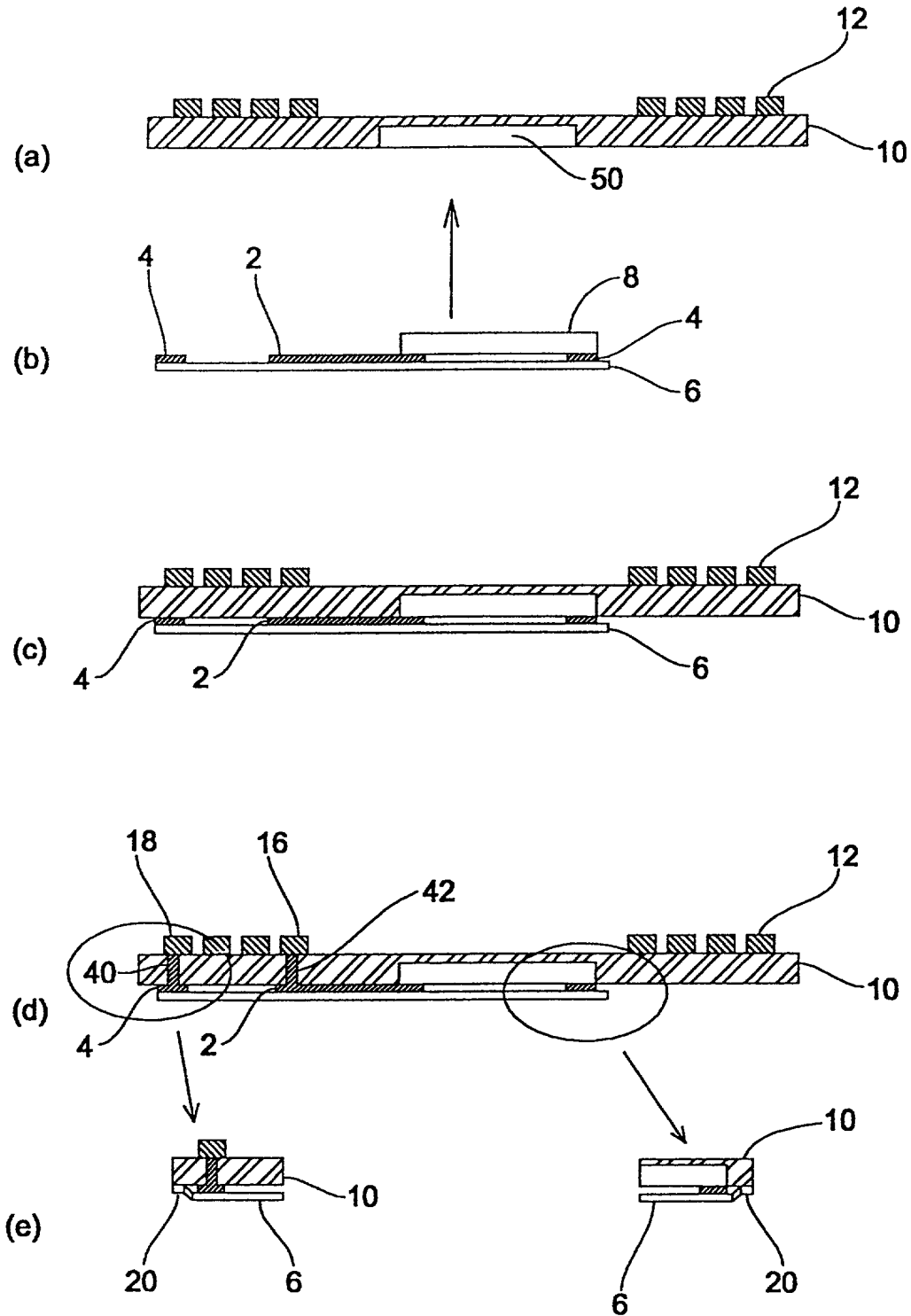
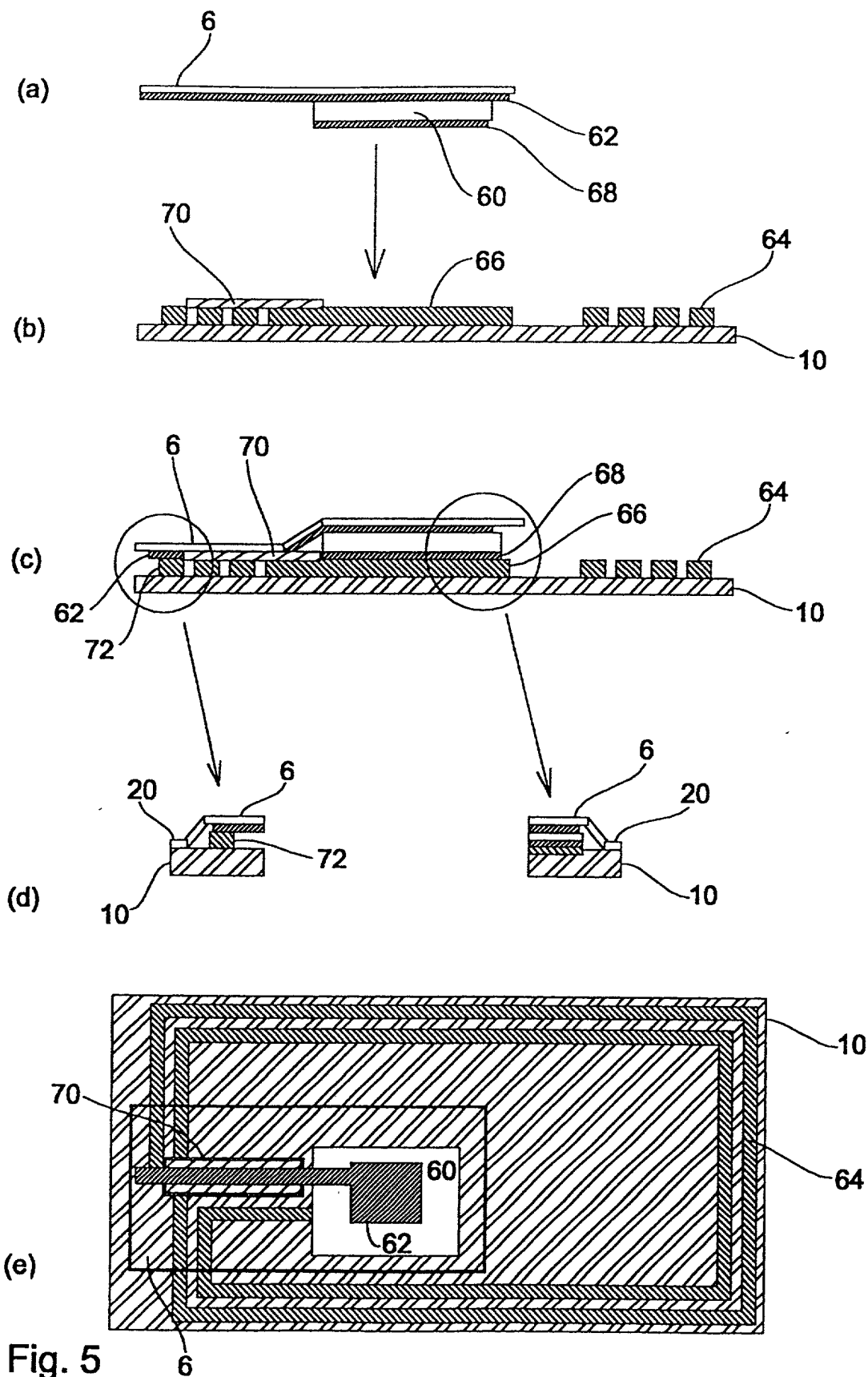


Fig. 4



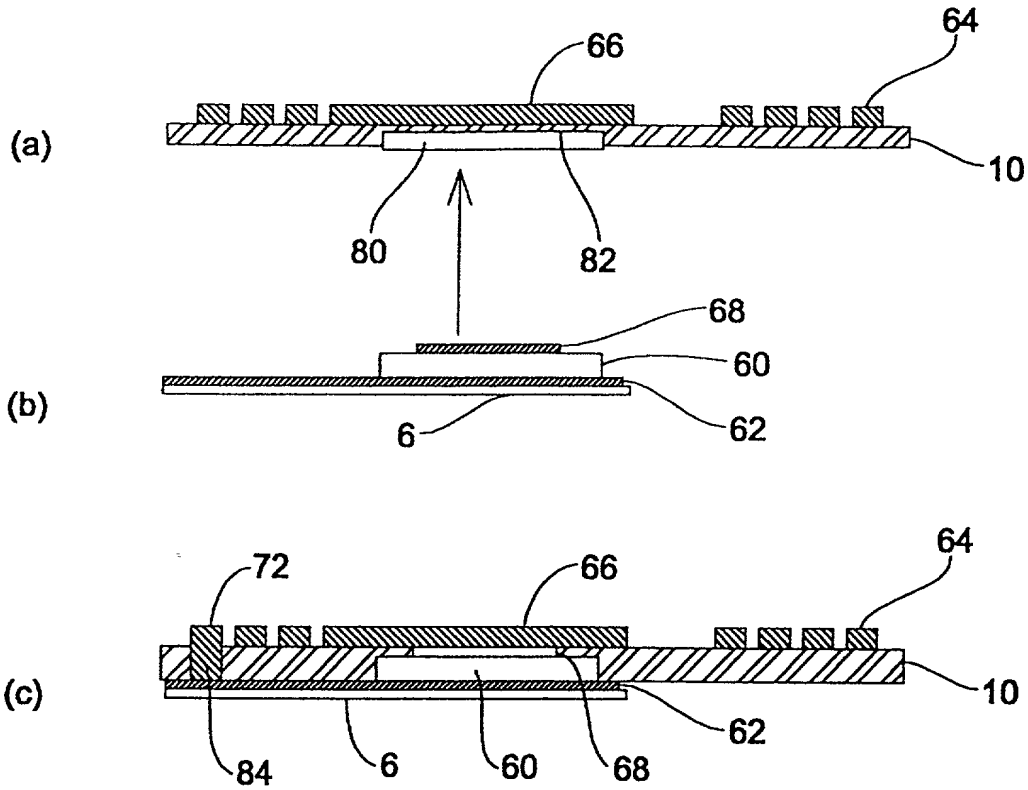


Fig. 6

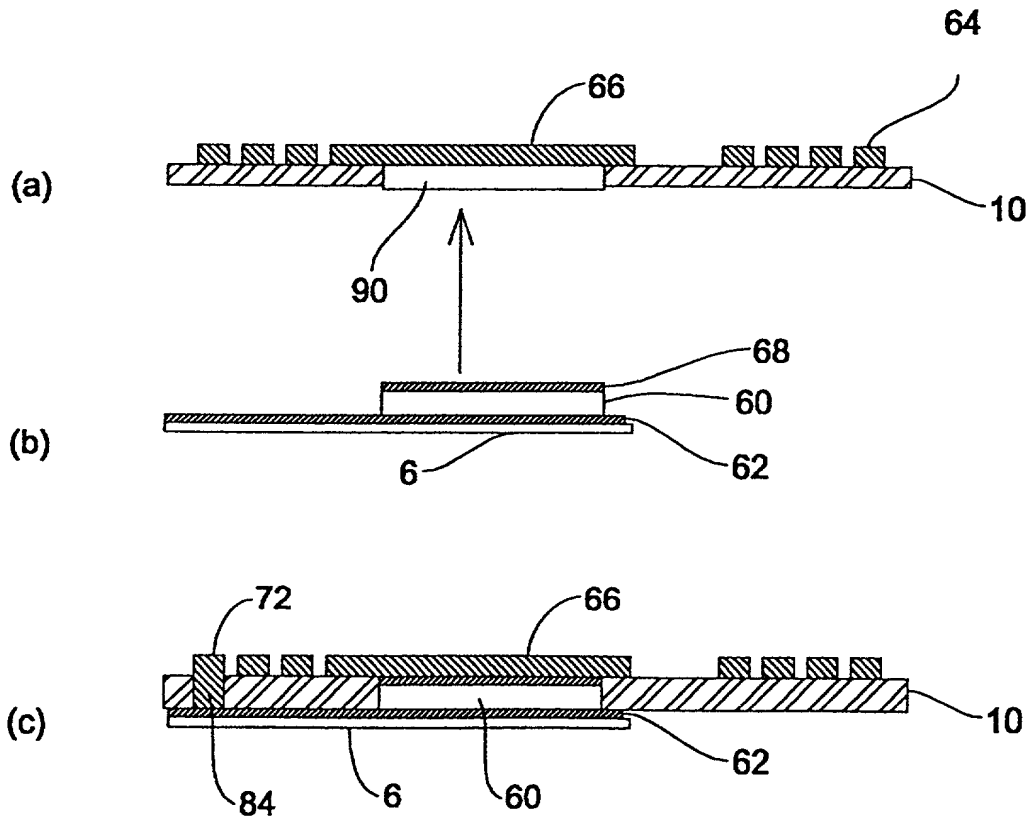


Fig. 7

09/787638
JC02 Rec'd PCT/PTO 20 MAR 2001

National Phase of PCT/EP99/07534 in U.S.A.

Title: Method for Producing a Microtransponder

Applicants: Andreas PLETTNER; Karl HABERGER

Translation of PCT Application PCT/EP99/07534
as originally filed

6/PRTS

09/787638
JC02 Rec'd PCT/PTO 20 MAR 2001

Method for Producing a Microtransponder

Description

5 The present invention relates to a method for producing a microtransponder, especially a microtransponder of the type having a circuit chip which contains the transponder electronics, and having in addition a coil metallization which acts as an antenna.

10

Due to the development of contact-bearing and contactless chip cards, a completely new and rapidly growing market for electronic microsystems has come into existence. Integrated circuits are nowadays installed not only in large devices or manually held systems, but they are installed so to speak "naked" in chip cards. A consistent further development leads to the so-called "throw-away electronics", the first representative of which was the telephone card. More recent fields of use for this so-called "throw-away electronics" are electronic labels which necessitate economy-priced chips or micromodules in economy-priced, ecologically acceptable supports. The simplest case of an electronic label would be a contactless module embedded between two pieces of paper, the contact module comprising an integrated circuit and an antenna coil.

15
20
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Transponder modules for electronic labels are disclosed in the Patent Abstracts of Japan, publication number 09297535A, relating to the Japanese application 08109052 and the Patent Abstracts of Japan, publication number 09293130A relating to the Japanese application 08109051. In the case of the electronic labels described in the above-mentioned publications an integrated circuit chip together with an antenna are cast

30

in a film-like resin. This film-like resin is then introduced into a metal mould where an outer resin is cast around the film-like resin.

- 5 The Patent Abstracts of Japan, publication number 090198481A, relating to Japanese application 08005845 disclose an electronic label in the case of which a circuit chip and a loop-type antenna are applied to a substrate, the outer end of the antenna being connected to a terminal on the integrated circuit via a bridging metallization which is conducted over the
10 windings of the antenna and which is separated from these windings by means of an insulating resin layer.

- The Patents Abstracts of Japan, publication No. 08216573A,
15 relating to Japanese application 07021785 describes a contactless IC card comprising a circuit chip and an antenna section. The circuit chip is attached to a circuit section provided on a polyester film, the antenna section being formed on this polyester film as well. By means of an adhesive layer, a second polyester film, which embeds the circuit
20 chip, is formed on the first polyester film. In addition, a third polyester film is applied to the surface of the second polyester film by means of a further adhesive layer.

- 25 In DE 19639902 A1 contactless chip cards and methods of producing the same are described. The chip cards described in this publication comprise an electrically insulating, one-piece card body having one or a plurality of openings on one side thereof. Furthermore, a conductor pattern is provided on
30 the surface of the card body, the conductors being directly applied to surface areas of the card body side provided with at least one opening, and the openings having arranged

therein one or a plurality of chips which are bonded to at least one of the conductors.

A survey of known methods of applying integrated circuit
5 chips to a substrate, e.g. by means of a flip-chip method, is contained in H. Reichl, et al: Packaging-Trends: "High-Tech im Kleinstformat", Elektronik 12/1998 (or SMT Nürnberg 98, Conference Proceedings).

10 Starting from this cited prior art, it is the object of the present invention to provide an economy-priced method, which permits the production of ultraflat microtransponders that are suitable to be used e.g. for electronic labels.

15 This object is achieved by a method according to claim 1.

The present invention provides a method for producing a microtransponder in the case of which an antenna metallization having a first and a second connecting end is first applied
20 to a support substrate. Furthermore, a connecting metallization is applied to a flexible support foil, whereupon a circuit chip having a first and a second connecting area is applied to the connecting metallization in such a way that at least the first connecting area of the circuit chip is connected
25 to the connecting metallization in an electrically conductive manner. The support substrate and the support foil are then joined in such a way that the connecting metallization is connected to the first connecting end of the antenna metallization in an electrically conductive manner and the
30 second connecting area of the circuit chip is connected to the second connecting end of the antenna metallization in an electrically conductive manner. Edge areas of the flexible support foil are then joined to neighbouring areas of the

support substrate so as to encapsulate at least the circuit chip.

It follows that the present invention provides a method for
5 producing a microtransponder in the case of which two modules
are initially formed, which are joined in the last step. The
first module comprises a support substrate, which may consist
e.g. of plastic material or of paper and on which the antenna
metallization, i.e. the coil, is formed. The second module
10 comprises a thin support substrate, which consists preferably
of plastic material, and which has applied thereto one or
more connecting metallizations and the circuit chip. These
two modules are then joined in such a way that the contacts
required for the electric connections between the coil and
15 the circuit chip are realized. The support foil is then used
for encapsulating the circuit chip and optional further areas
of the coil metallization and of the connecting metalliza-
tions, respectively, by joining edge areas of the support
foil with neighbouring areas of the support substrate by
20 means of welding or by means of an adhesive so that espe-
cially the circuit chip can be protected against external in-
fluences.

According to the present invention, the two modules can first
25 be processed separately from one another so that one module
can be processed without taking into consideration the re-
spective other module. The two modules can then be joined in
such a way that, when they are being joined, all the neces-
sary electric connections will be established. Through-
30 contacts through the support substrate, which are only re-
quired in the case of some embodiments, have to be estab-
lished in a separate step before or after the joining of the
two modules. When the two modules have been joined, the thin

support foil, which, on the one hand, serves to handle the circuit chip and the connecting metallization, is used in accordance with the present invention for encapsulating at least the circuit chip and preferably also the areas in which
5 the connections between the connecting metallization and the antenna metallization are realized, by joining edge areas of this thin support foil to the support substrate by means of welding or by means of an adhesive. This encapsulation is carried out preferably in a vacuum or making use of a protective gas so as to prevent an inclusion of possibly detrimental substances.
10

Embodiments and further developments of the present invention are defined in the dependent claims.

15

In the following, preferred embodiments of the present invention will be explained in detail making reference to the drawings enclosed, in which respective identical elements are designated by identical reference numerals.

20

Fig. 1a) to 1e) show a schematic representation for illustrating a first embodiment of the method according to the present invention;

25

Fig. 2a) to 2d) show a schematic representation for illustrating a second embodiment of the method according to the present invention;

30

Fig. 3a) to 3e) show a schematic representation for illustrating a third embodiment of the method according to the present invention;

Fig. 4a) to 4e) show a schematic representation for illustrating a fourth embodiment of the method according to the present invention;

5 Fig. 5a) to 5e) show a schematic representation for illustrating a fifth embodiment of the method according to the present invention;

10 Fig. 6a) to 6c) show a schematic representation for illustrating a sixth embodiment of the method according to the present invention;

15 Fig. 7a) to 7c) show a schematic representation for illustrating a seventh embodiment of the method according to the present invention.

20 Making reference to Fig. 1, the first embodiment of the method according to the present invention will now be explained in detail. As has been stated above, two separate modules are first produced in the case of the method for producing a microtransponder according to the present invention. The first module produced is shown in Fig. 1a). In the case of this embodiment, a first connecting metallization 2 and a second connecting metallization 4 are first applied to a thin support foil 6, which consists preferably of plastic material, so as to produce this first module, which can also be referred to as circuit chip module. Subsequently, a circuit chip 8 is applied to the connecting metallizations 2 and 4. The circuit chip 8 comprises the integrated circuit required for the microtransponder and is provided with two connecting areas on or in one main surface thereof; for operating the microtransponder, these connecting areas must be connected to respective connecting ends of a coil antenna metallization.

25

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The circuit chip 8 is applied to the connecting metallization 2 in such a way that the first connecting area thereof is connected to the first connecting metallization 2 in an electrically conductive manner, whereas the second connecting area thereof is connected to the connecting metallization 4 in an electrically conductive manner. This results in the structural design of the first module shown in Fig. 1a).

This first module is produced from extremely thin materials. This is important in view of the fact that, when the microtransponder has been finished, the circuit chip 8 with the support foil 6 should not perceptibly project beyond a support substrate on which the coil metallization is arranged. The circuit chip and the foil preferably have a thickness of less than 50 μm .

The connecting metallizations 2 and 4, which may consist e.g. of Al, Cu and the like, can be applied to the foil by arbitrary methods, e.g. by cladding and subsequent structuring, by evaporation or sputtering and subsequent structuring, or alternatively by evaporation or sputtering making use of a shadow mask so as to apply lines which are already structured. The connecting metallizations may have a thickness of less than 1 μm , since the conductor tracks of the connecting metallizations can be implemented such that they are short and broad. When the connecting metallizations 2 and 4 have been finished, the circuit chip 8 is placed on the contact areas of the connecting metallizations and is connected thereto in an electrically conductive manner; this can be done e.g. by means of thermocompression, anisotropic conductive adhesives or ultrasonic compression.

In Fig. 1b) the second module is shown, which comprises a support substrate 10 and an antenna metallization 12 applied to a main surface of the support substrate 10. The support substrate may consist e.g. of plastic material or paper. The antenna metallization 12, which has the form of a coil, can again be formed on the support substrate 10 by arbitrary known methods. The coil metallization can e.g. be formed by etching a cladding. Alternatively, a wire can be placed onto the support substrate 10 such that a coil is formed. According to another alternative, a metal, e.g. Cu, Al and the like, can be applied to the support substrate 10 by evaporation and structured subsequently. In order to obtain an adequate thickness of the coil metallization 12 the evaporated metallization can subsequently be thickened by means of an electroplating technique. As can additionally be seen in Fig. 1b), a local thin insulating layer 14 is produced, e.g. by means of a printing process, in an area of the coil metallization 12. This local insulating layer is produced in an area onto which the second connecting metallization 4 will be placed later on so as to prevent a short circuit between the second connecting metallization 4 and the coil metallization 12.

At this point reference should be made to the fact that, alternatively to the application of the insulating layer 14 to the coil metallization 12, this local insulating layer may also be formed on corresponding areas of the first module, e.g. by means of a suitable printing process or by surface oxidation of the metallization. Since the lines of the first module are very thin in comparison with the antenna metallization, which may have a thickness of e.g. 4 to 30 μm , it may be more advantageous to form the insulating layer on the first module, which is shown in Fig. 1a). The insulating

layer 14 can consist of an acrylic lacquer having a thickness of 0.2 to 2 μm , this acrylic lacquer being then locally removed at the future contact points; this is done by means of a thermal process. If the local insulating layer is formed on the first module, this can be done prior to or subsequent to the application of the circuit chip 8 to the connecting metallizations 2 and 4.

The first module and the second module are now joined in a subsequent step, as shown in Fig. 1c). In so doing, the first connecting metallization 2 is connected to a first connecting end 16 of the antenna metallization 12 in an electrically conductive manner, whereas the second connecting metallization 4 is connected to a second connecting end 18 of the antenna metallization in an electrically conductive manner. In the embodiment shown in Fig. 1, an isoplanar contact is obtained in this way. As can be seen in Fig. 1d), the support foil 6 is then connected along its edges to the support substrate 10 in such a way that, in the embodiment shown, the circuit chip 8 as well as the connecting areas between the antenna metallization and the connecting metallization are encapsulated. This can be achieved by bending the edges of the thin support foil 6 towards the support substrate 10 and by subsequently joining the foil areas abutting on the support substrate 10 to the support substrate 10 by means of welding or by means of an adhesive, as can be seen in Fig. 1d). It follows that, according to the present invention, an encapsulation of the circuit chip and, in the case of the embodiment shown, of the connection points can be accomplished in a simple manner so as to provide protection against external influences. This connection process between the support foil 6 and the support substrate 10 is preferably carried out in a vacuum.

A top view of the microtransponder produced by means of the above method is shown in Fig. 1e). In this top view, especially the shape of the connecting metallizations 2 and 4 and the arrangement of the insulating layer 14 can be seen.

Fig. 2 shows a schematic representation of a second embodiment of the production method according to the present invention. The method shown in Fig. 2 corresponds essentially to the method described with reference to Fig. 1, the support substrate 10 having, however, provided therein an opening/recess 30 into which the circuit chip 8 is introduced when the first and second modules are being joined. The opening 30 can be formed in the support substrate 10 by means of arbitrary known methods. Since the support foil 6 and the thin connecting metallization 2 provided thereon are flexible, the shape of the support foil 6 shown at 32 in Fig. 2c) is obtained. One advantage of this embodiment of the method according to the present invention is that the opening 30 permits an improved protection of the circuit chip 8 and that, in addition, the circuit chip can be fixed more effectively. The edge areas of the support foil 6 are again joined to neighbouring areas of the support substrate 10 by means of an adhesive or by means of welding so as to achieve an encapsulation of the circuit chip.

In Fig. 3 a third embodiment of the method according to the present invention is schematically shown. In Fig. 3a) the second module is shown, which corresponds to the above-described second module. In Fig. 3b) the first module is shown, which also corresponds to the above-described first module. Other than in the case of the above-described embodiments, the first and the second module are now, however,

joined in such a way that the circuit chip 8 will be positioned on the surface of the support substrate 10 which is located opposite the surface of the support substrate 10 having the antenna metallization 12 formed thereon, cf. Fig. 3c). It follows that in the third embodiment shown, an electrically conductive connection between the first and second connecting ends of the antenna metallization 12 and the first and second connecting metallizations 2 and 4 is not yet established simultaneously with the joining of the first and second modules. In order to realize this electrically conductive connection, through-contacts 40 and 42, respectively, are established, cf. Fig. 3d). By means of the through-contact 42 an electrically conductive connection is established between the first connecting metallization 2 and the first connecting end 16 of the antenna metallization 12, whereas by means of the through-contact 40 an electrically conductive connection is established between the second connecting metallization 4 and the second connecting end 18 of the antenna metallization 12.

In order to establish the through-contacts, thermocompression methods can be used by way of example. Alternatively, the through-contacts can be produced by means of an ultrasonic compression, by means of welding or by means of soldering. In this respect, it should be pointed out that the through-contacts may already be produced when the two modules have not yet been joined, i.e. in the stage of the second module which is shown in Fig. 3a), so that, when the two modules are being joined, the respective electrically conductive connections between the through-contacts and the connecting metallizations will be produced. As can be seen in Fig. 3e), the edge areas 20 of the support foil are again joined to neighbouring areas of the support substrate 10 by means of

welding or by means of an adhesive, so as to encapsulate the circuit chip and, in the embodiment shown, additional areas.

The fourth embodiment of the method according to the present invention shown in Fig. 4 differs from the embodiment which has been described with respect to Fig. 3 insofar as the surface of the support substrate 10 located opposite the antenna metallization 12 has formed therein an opening 50 into which the circuit chip 8 is introduced when the first and second modules are being joined. As can be seen in Fig. 4c, this permits an isoplanarity of the connecting metallizations 2 and 4. As in the case of the embodiment according to Fig. 3, through-contacts 40, 42 are again produced for establishing an electrically conductive connection between the connecting metallizations 2 and 4 and the first and second connecting ends 16 and 18 of the antenna metallization 12. Furthermore, also according to the fourth embodiment, the edge areas 20 of the support foil 6 are joined to neighbouring areas of the support substrate 10 by means of welding or by means of an adhesive so as to effect an encapsulation.

In the case of the method shown in Fig. 5, a circuit chip 60 is used, which is provided with a first connecting area on a first main surface thereof and with a second connecting area on a second main surface thereof. The first module shown in Fig. 5a) is now formed by applying a single connecting metallization 62 to a support foil 6. The circuit chip 60 is applied to the connecting metallization 62, an electrically conductive connection being established between the connecting area of the circuit chip 60 and the connecting metallization 62 e.g. by means of conductive adhesives or by means of soldering.

Fig. 5b) shows the second module; for producing this second module, an antenna metallization 64 is first applied to a support substrate 10. As can be seen in Fig. 5b), the antenna metallization 64 has a preferably enlarged second connecting end 66, the circuit chip 60, whose lower surface may be provided with a metallization 68 thickening the connecting area, being applied to this second connecting end 66 when the first and second modules are being joined. As has already been explained with reference to Fig. 1, a local insulating layer 70 is formed on respective areas of the antenna metallization 64 also in the case of the embodiment shown in Fig. 5 so as to prevent later on a short circuit between the connecting metallization 62 and the antenna metallization 64.

The first module is now connected to the second module, cf. Fig. 5c), a contact between the metallization 68, i.e. the second connecting area on the lower surface of the circuit chip 60, and the second connecting end of the antenna metallization 66 being established simultaneously, and an electrically conductive connection between the connecting metallization 62 and the first connecting end 72 of the antenna metallization 64 being established simultaneously. As can be seen in the detail representations shown in Fig. 5d), the edge areas 20 of the support foil 6 are connected, i.e. joined by means of welding or by means of an adhesive, to corresponding neighbouring areas of the support substrate 10 also in the case of this embodiment. Fig. 5e) shows a top view of the resultant microtransponder.

In the sixth embodiment of the method according to the present invention, which is schematically shown in Fig. 6, a first module is again prepared, which essentially corresponds to the first module shown in Fig. 5. This first module

is shown in Fig. 6b). The second module differs from the module described with reference to Fig. 5 insofar as an opening 80 is formed in the main surface of the support substrate 10 facing away from the antenna metallization 64, Fig. 6a). As can be seen in Fig. 6c), the circuit chip 60 is introduced in this opening 80 when the two modules according to this embodiment are being joined. For establishing an electric contact between the connecting area, or the reinforcement 68, arranged on the upper surface of the circuit chip and the second connecting end 66 of the antenna metallization 64, it is necessary to eliminate, preferably by means of a thermally supported method, the web 82 of the support substrate arranged above the opening 80, so as to establish an electrically conductive connection between the connecting area arranged on the upper surface of the circuit chip 60 and the second connecting end 66 of the antenna metallization 64. Furthermore, a through-contact 84 is produced so as to establish an electrically conductive connection between the connecting metallization 62 and the first connecting end 72 of the antenna metallization 64. Also in the case of this embodiment, the edges of the support foil 6 are joined to the support substrate 10 by means of welding or by means of an adhesive so as to obtain an encapsulation.

Also in the embodiment which is schematically shown in Fig. 7, a circuit chip 60 with double-sided contacting is used. Other than in the case of the method described with reference to Fig. 6, the support substrate 10 has now provided therein an opening 90 which extends through the whole support substrate 10 up to the second connecting end 66 of the coil metallization 64. The rest of the method for producing the microtransponder according to the embodiment shown in Fig. 7 corresponds essentially to the method which has been de-

scribed with reference to Fig. 6, but the heat treatment for eliminating a web above the opening 90 can now be dispensed with, since such a web does not exist. The other steps correspond to the steps which have been described with reference
5 to Fig. 6.

It should be pointed out that the second connecting end 66 of the antenna metallization 64 may cover the circuit chip 60 completely or partially. Furthermore, the metallization 68 on
10 the circuit chip 60 may cover the circuit chip completely or partially; a person skilled in the art will also be aware of the fact that, with the exception of the connecting area of the circuit chip 60, a passivation layer is arranged between the metallization 68 and the circuit chip 60.

15 It follows that the present invention provides a simple technique for producing a microtransponder in the case of which the production of the antenna module and the production of the circuit chip module are completely separated. The circuit
20 chip module can be implemented such that it is much thinner than the antenna module. Various production techniques can be used for producing the antenna module and for producing the circuit chip module. Due to the fact that the circuit chip is encapsulated or that large areas thereof are covered by a
25 metallization, good light protection can be achieved. The methods according to the present invention are preferably executed such that the individual modules are formed on an endless material and are then sequentially supplied to a processing station in which the modules are joined. The re-
30 spective metallic layers may consist of a ferromagnetic material so as to permit, if necessary, magnetic handling of the individual modules or of the finished microtransponder. For handling the thin circuit chip module, the circuit chip mod-

ule may be supported by an additional support so as to stabilize it, whereby distortions or even rolling up due to internal mechanical stress can be avoided. The encapsulation of the circuit chip and of additional optional areas is preferably carried out in a vacuum or while a protective gas, e.g. a forming gas, is being supplied.

TOP SECRET

Claims

1. A method for producing a microtransponder comprising the
5 following steps:

applying an antenna metallization (12; 64) having a first
(16; 72) and a second (18; 66) connecting end to a support
substrate (10);

10

applying a connecting metallization (2, 4; 62) to a flexi-
ble support foil (6);

15

a) applying a circuit chip (8; 60) having a first and a
second connecting area to said connecting metallization
(2, 4; 62) in such a way that at least the first con-
necting area of the circuit chip is connected to the
connecting metallization (2; 62) in an electrically
conductive manner;

20

b) joining the support substrate (10) and the support foil
(6) in such a way that the connecting metallization (2;
62) is connected to the first connecting end (16; 72)
of the antenna metallization (12; 64) in an electri-
cally conductive manner, and that the second connecting
area of the circuit chip (8; 60) is connected to the
second connecting end (18; 66) of the antenna metalli-
zation (12; 64) in an electrically conductive manner;
and

25

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c) joining edge areas (20) of the flexible support foil
(6) to neighbouring areas of the support substrate (10)
so as to encapsulate at least the circuit chip (8; 60).

2. A method according to claim 1, wherein the edge areas (20) of the flexible support foil (6) are welded to the neighbouring areas of the support substrate (10).

5

3. A method according to claim 1, wherein the edge areas (20) of the flexible support foil (6) are joined to the neighbouring areas of the support substrate (10) by means of an adhesive.

10

4. A method according to one of the claims 1 to 3, wherein in step b) a first and a second connecting metallization (2, 4) are applied to the flexible support foil (6), and wherein in step c) the circuit chip (8), which is provided with said first and second connecting areas on a first main surface thereof, is applied to said first and said second connecting metallizations (2, 4) in such a way that the first connecting area is connected to the first connecting metallization (2) in an electrically conductive manner and the second connecting area is connected to the second connecting metallization (4) in an electrically conductive manner, the second connecting area being, in step d), connected via the second connecting metallization (4) to the second connecting end (18) of the antenna metallization (12) in electrically conductive manner.

25

5. A method according to one of the claims 1 to 3, wherein the circuit chip (60) applied in step c) has the first connecting area on a first main surface thereof and the second connecting area on a second main surface thereof, which is located opposite said first main surface.

30

6. A method according to claim 4, wherein in step d) the support foil (6) and the support substrate (10) are joined in such a way that the antenna metallization (12) and the circuit chip (8) are arranged on the same main surface of the support substrate (10).
7. A method according to claim 4, wherein the circuit chip (8) is introduced in step d) in an opening (30) in the support-substrate main surface to which the antenna metallization (12) has been applied.
8. A method according to claim 6 or 7, wherein an insulator structure (14) is provided so as to insulate the second connecting metallization (4) from the antenna metallization (12) with the exception of the location at the second connecting end (18) of the antenna metallization (12).
9. A method according to claim 4, wherein the support foil (6) and the support substrate (10) are joined in step d) in such a way that the antenna metallization (12) and the circuit chip (8) are arranged on opposed main surfaces of the support substrate (10), the first and second connecting metallizations (2, 4) being connected by means of through-contacts (40, 42) to the first and second connecting ends (16, 18) of the antenna metallization (12).
10. A method according to claim 4, wherein in step d) the circuit chip (8) is introduced in an opening (50) provided in the main surface of the support substrate (10) which is located opposite the main surface having the antenna metallization (12) applied thereto, the first and second connecting metallizations (2, 4) being connected

by means of through-contacts (40, 42) to the first and second connecting ends (16, 18) of the antenna metallization (12).

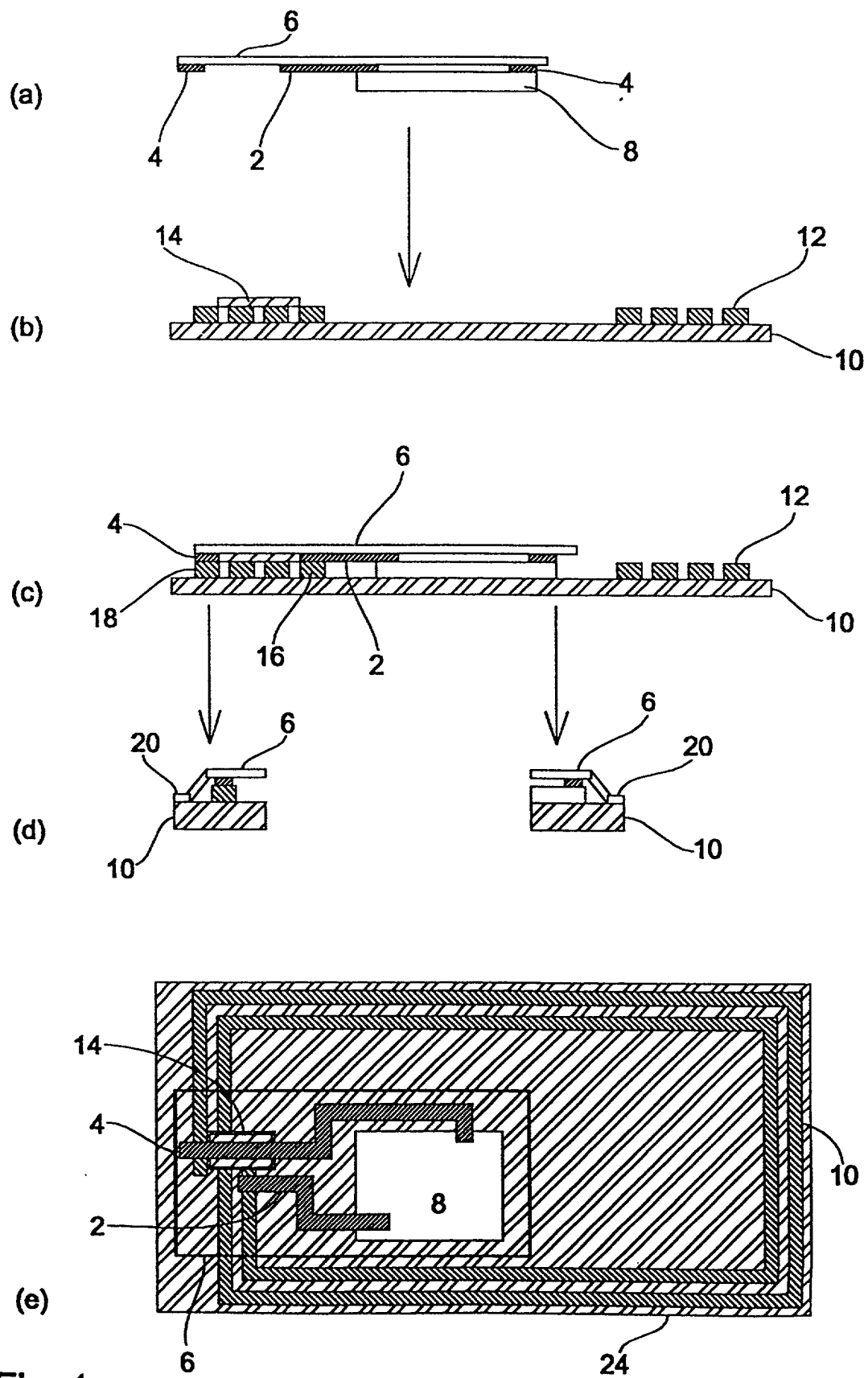
- 5 11.A method according to claim 5, wherein the support foil (6) and the support substrate (10) are joined in step d) in such a way that the antenna metallization (64) and the circuit chip (60) are arranged on the same main surface of the support substrate (10).
- 10 12.A method according to claim 5, wherein in step d) the circuit chip (60) is introduced into an opening (80; 90) provided in the main surface of the support substrate (10) which is located opposite the main surface having
- 15 the antenna metallization (64) applied thereto, the connecting metallization (62) being connected via a through-contact (84) to the first connecting end (72) of the antenna metallization (64).
- 20 13.A method according to one of the claims 1 to 12, wherein step e) is executed in a vacuum or making use of a protective gas.

Method for Producing a Microtransponder

Abstract

5 According to a method for producing a microtransponder, an antenna metallization (12) having a first (16) and a second (18) connecting end is first applied to a support substrate (10) so as to form a first module. A connecting metallization (2, 4) is applied to a flexible support foil (6), whereupon a
10 circuit chip (8) having a first and a second connecting area is applied to said connecting metallization (2, 4) in such a way that at least the first connecting area of the circuit chip (8) is connected to said connecting metallization (2, 4) in an electrically conductive manner. The flexible support
15 foil (6) having the circuit chip (8) applied thereto represents a second module. The first and the second module are subsequently joined in such a way that the connecting metallization (2, 4) is connected to the first connecting end of the antenna metallization (12) in an electrically conductive
20 manner and the second connecting area of the circuit chip (8) is connected to the second connecting end of the antenna metallization (12) in an electrically conductive manner. Finally, edge areas of the flexible support foil (6) are joined to neighbouring areas of the support substrate (10) so as to
25 encapsulate at least the circuit chip (8).

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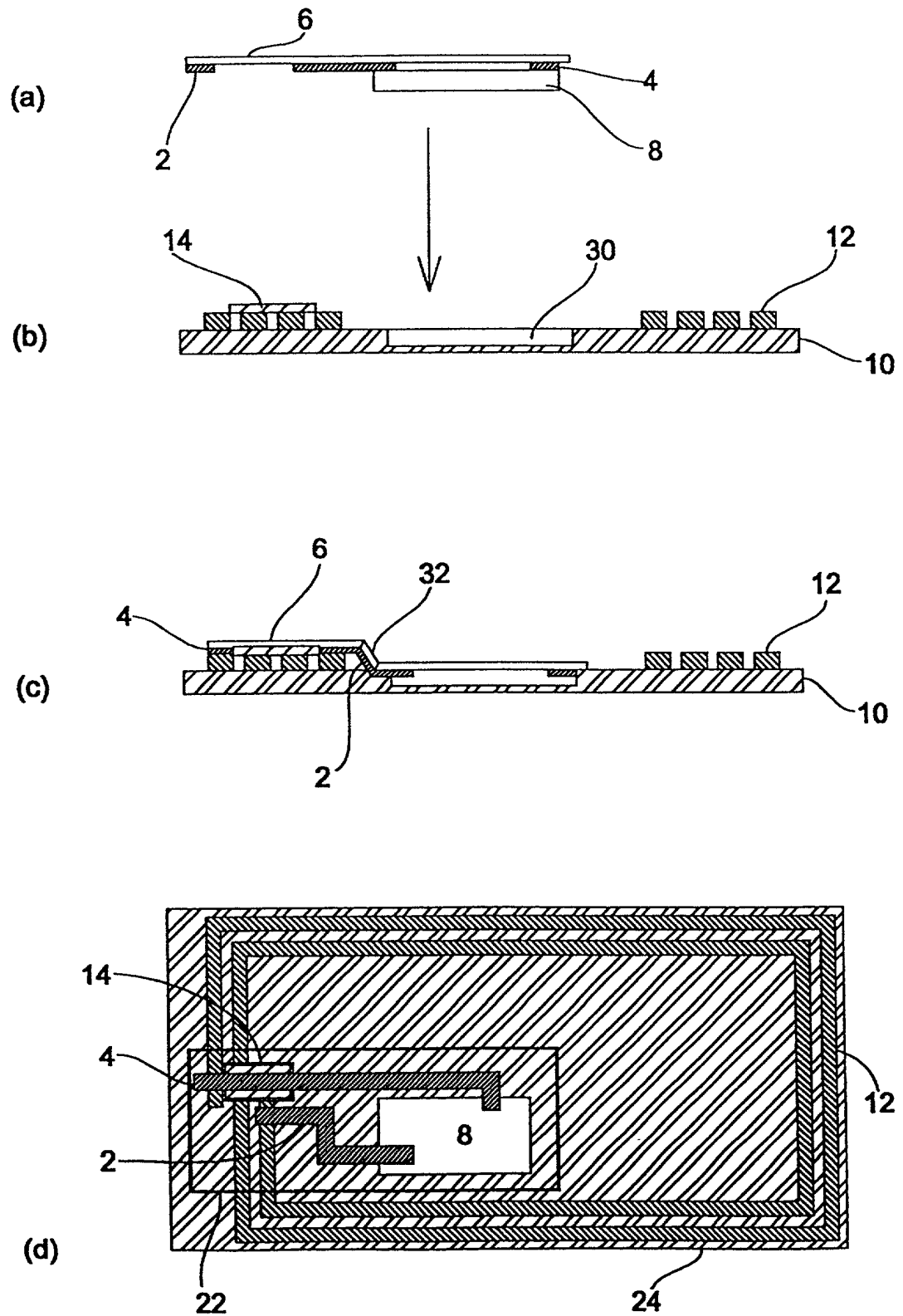


Fig. 2

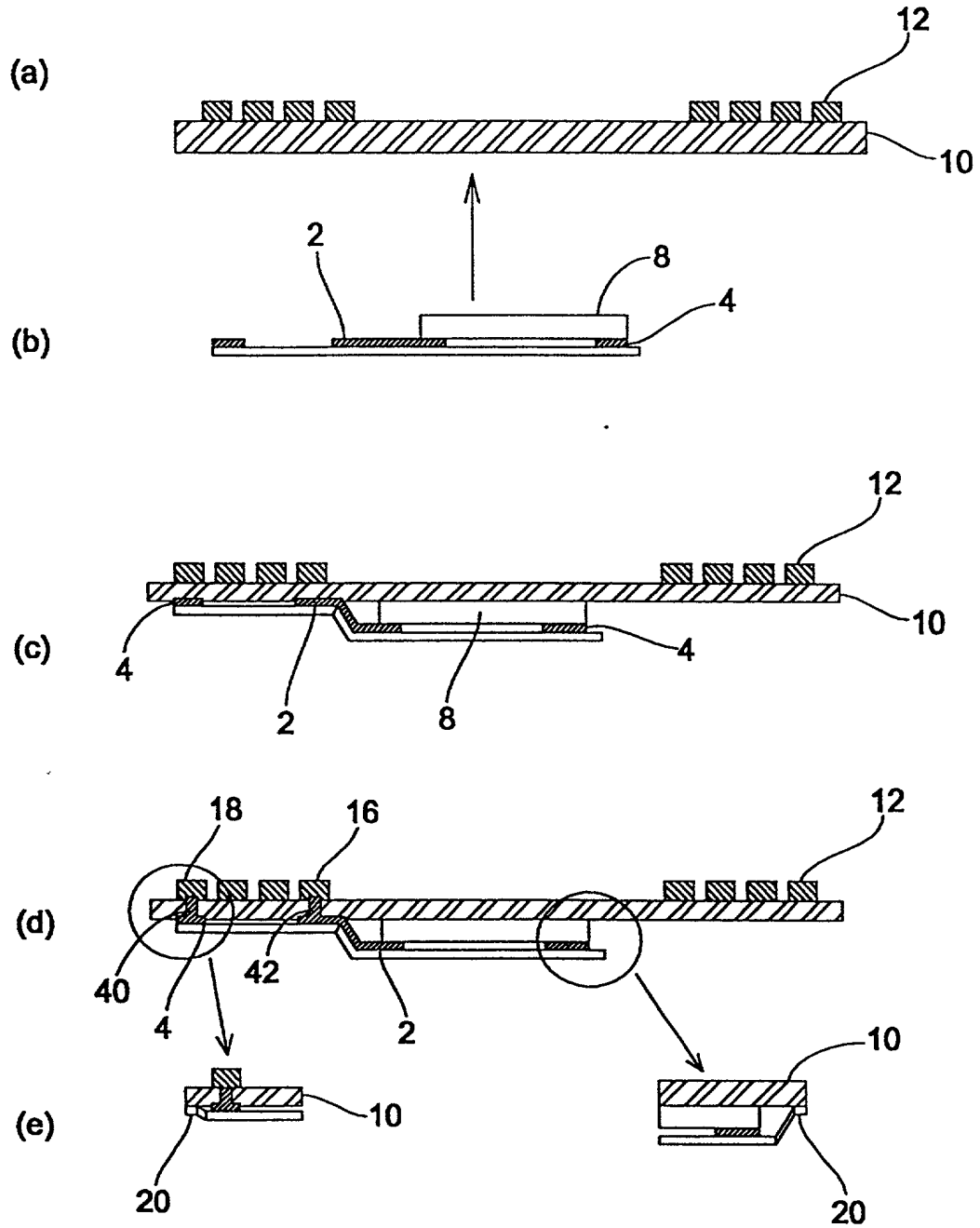


Fig. 3

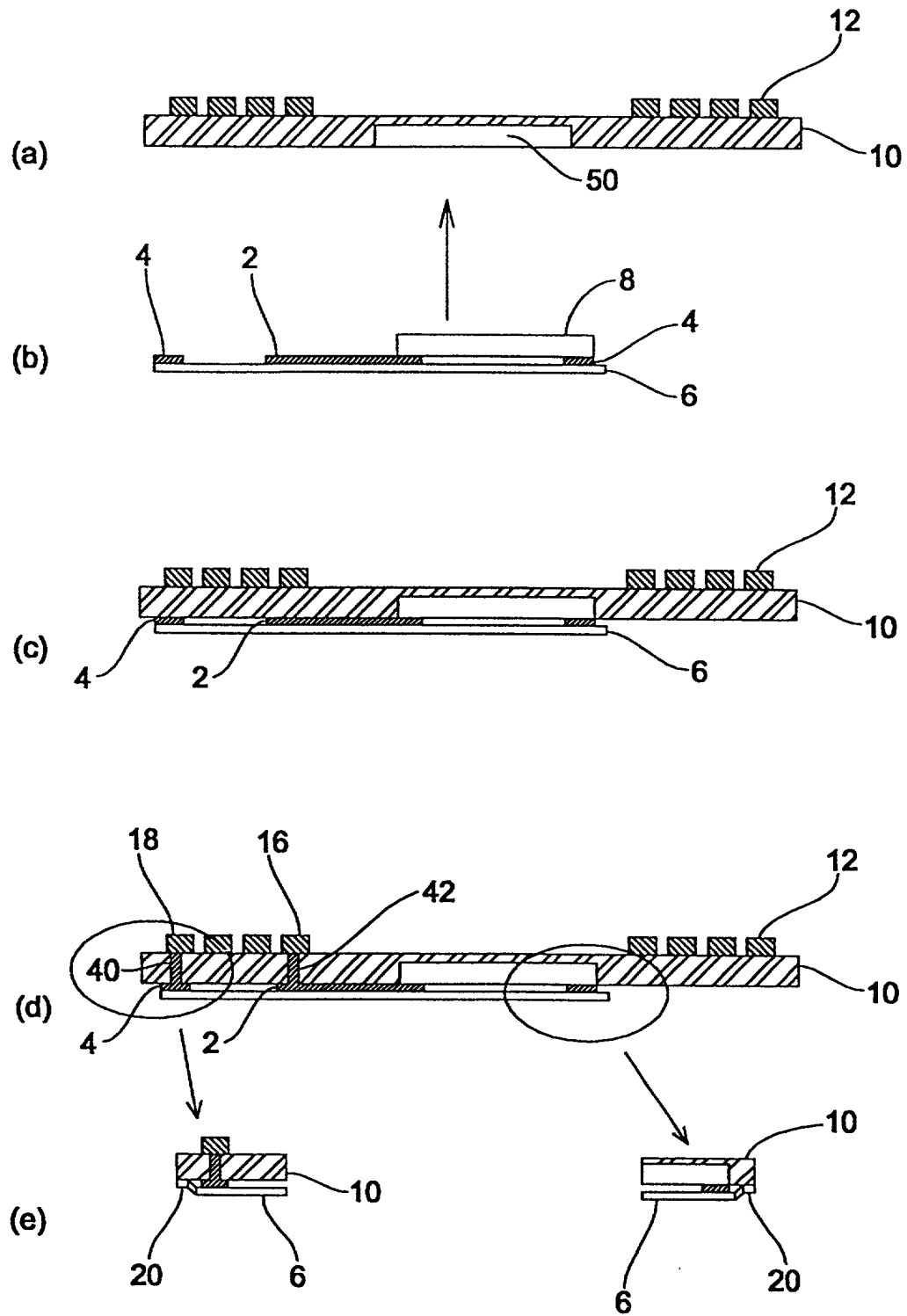
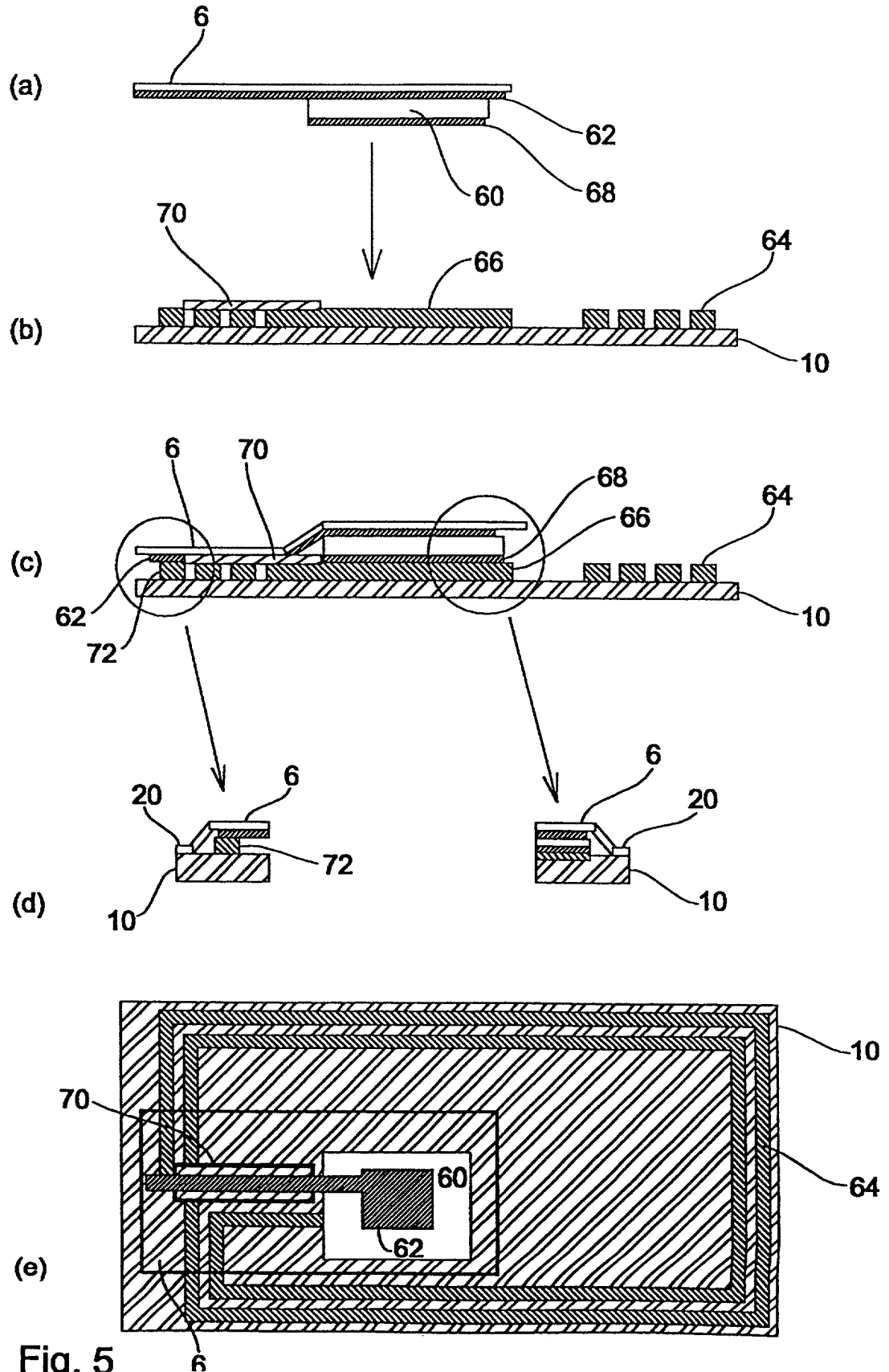


Fig. 4



- 6/6 -

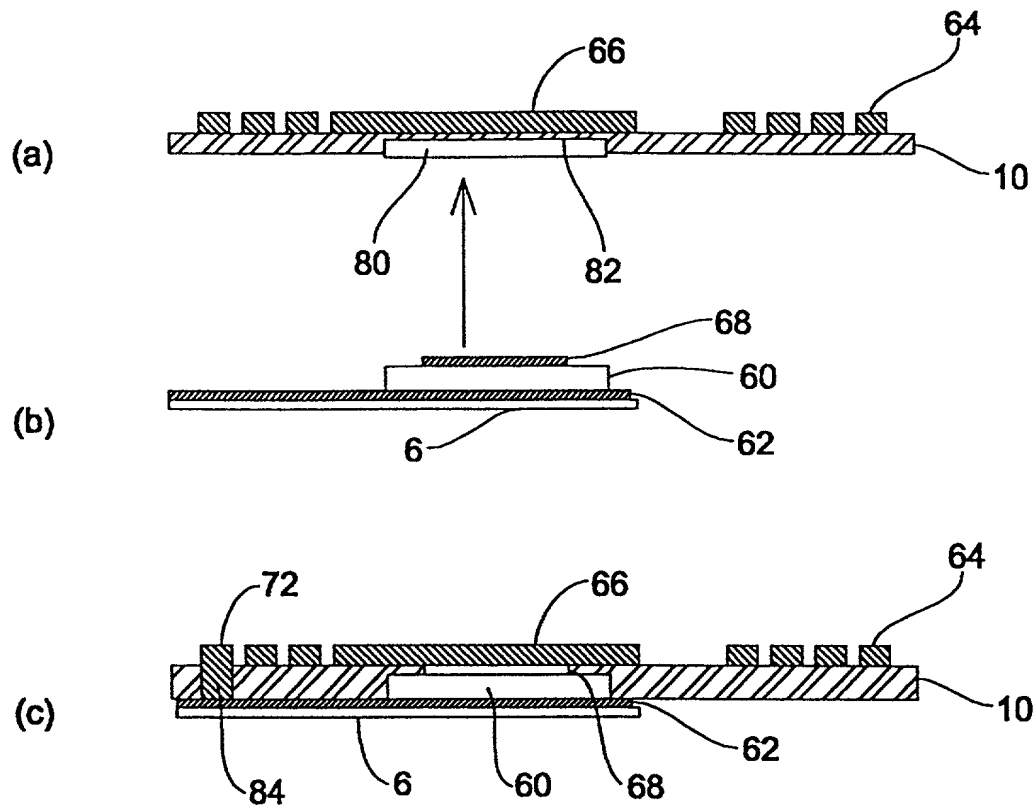


Fig. 6

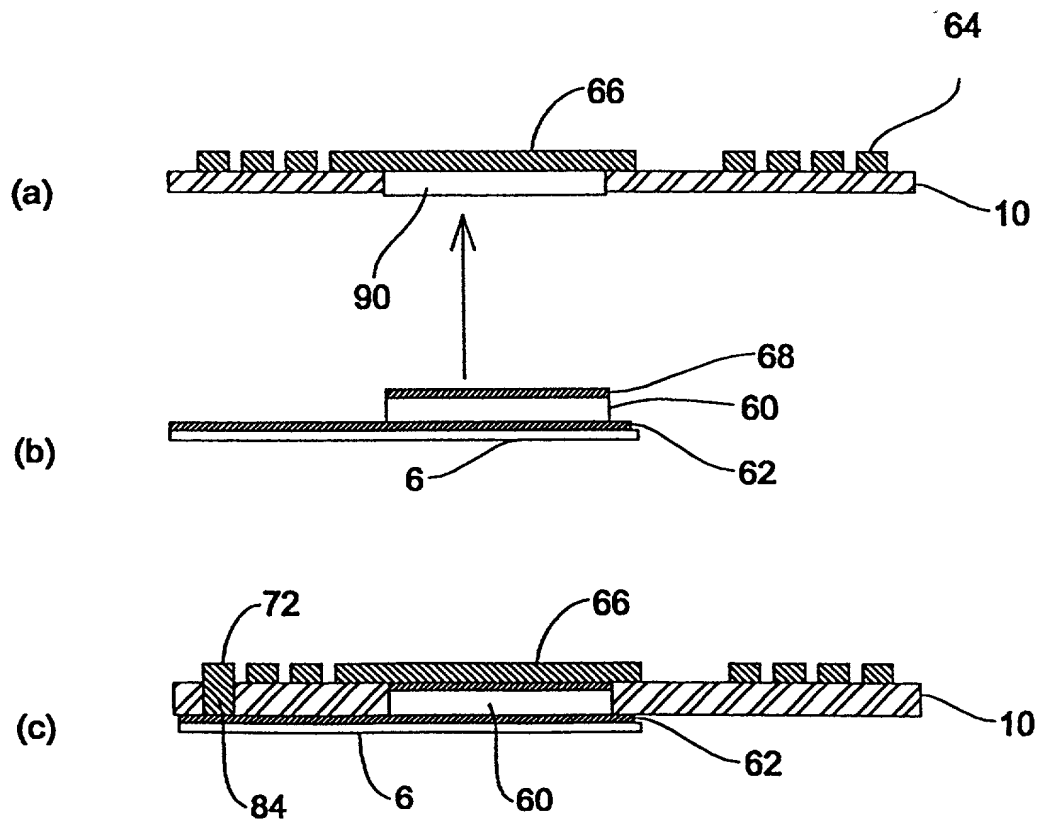


Fig. 7

09/787638

JC02 Rec'd PCT/PTO 20 MAR 2001

National Phase of PCT/EP99/07534 in U.S.A.

Title: Method for Producing a Microtransponder

Applicants: Andreas PLETTNER; Karl HABERGER

Annotated copy of Final version of PCT/EP99/07534

Method for Producing a MicrotransponderDescription5 BACKGROUND OF THE INVENTIONField of the Invention

10 The present invention relates to a method for producing a microtransponder, especially a microtransponder of the type having a circuit chip which contains the transponder electronics, and having in addition a coil metallization which acts as an antenna.

15 Description of Prior Art

20 Due to the development of contact-bearing and contactless chip cards, a completely new and rapidly growing market for electronic microsystems has come into existence. Integrated circuits are nowadays installed not only in large devices or manually held systems, but they are installed so to speak "naked" in chip cards. A consistent further development leads to the so-called "throw-away electronics", the first representative of which was the telephone card. More recent fields
25 of use for this so-called "throw-away electronics" are electronic labels which necessitate economy-priced chips or micromodules in economy-priced, ecologically acceptable supports. The simplest case of an electronic label would be a
30 contactless module embedded between two pieces of paper, the contact module comprising an integrated circuit and an antenna coil.

Transponder modules for electronic labels are disclosed in the Patent Abstracts of Japan, publication number 09297535A, relating to the Japanese application 08109052 and the Patent Abstracts of Japan, publication number 09293130A relating to
5 the Japanese application 08109051. In the case of the electronic labels described in the above-mentioned publications an integrated circuit chip together with an antenna are cast in a film-like resin. This film-like resin is then introduced into a metal mould where an outer resin is cast around the
10 film-like resin.

The Patent Abstracts of Japan, publication number 090198481A, relating to Japanese application 08005845 disclose an electronic label in the case of which a circuit chip and a loop-
15 type antenna are applied to a substrate, the outer end of the antenna being connected to a terminal on the integrated circuit via a bridging metallization which is conducted over the windings of the antenna and which is separated from these windings by means of an insulating resin layer.

20 The Patents Abstracts of Japan, publication No. 08216573A, relating to Japanese application 07021785 describes a contactless IC card comprising a circuit chip and an antenna section. The circuit chip is attached to a circuit section
25 provided on a polyester film, the antenna section being formed on this polyester film as well. By means of an adhesive layer, a second polyester film, which embeds the circuit chip, is formed on the first polyester film. In addition, a third polyester film is applied to the surface of the second
30 polyester film by means of a further adhesive layer.

In DE 19639902 A1 contactless chip cards and methods of producing the same are described. The chip cards described in

1 this publication comprise an electrically insulating, one-
piece card body having one or a plurality of openings on one
side thereof. Furthermore, a conductor pattern is provided on
the surface of the card body, the conductors being directly
5 applied to surface areas of the card body side provided with
at least one opening, and the openings having arranged
therein one or a plurality of chips which are bonded to at
least one of the conductors.

10 A survey of known methods of applying integrated circuit
chips to a substrate, e.g. by means of a flip-chip method, is
contained in H. Reichl, et al: Packaging-Trends: "High-Tech
im Kleinstformat", Elektronik 12/1998 (or SMT Nürnberg 98,
Conference Proceedings).

15

SUMMARY OF THE INVENTION

~~Starting from this cited prior art, it~~ It is the object of
20 the present invention to provide an economy-priced method,
which permits the production of ultraflat microtransponders
that are suitable to be used e.g. for electronic labels.

This object is achieved by a method ~~according to claim 1.~~

25

~~The present invention provides a method for~~ producing a mi-
crotransponder in the case of which an antenna metallization
having a first and a second connecting end is first applied
to a support substrate. Furthermore, a connecting metalliza-
30 tion is applied to a flexible support foil, whereupon a cir-
cuit chip having a first and a second connecting area is ap-
plied to the connecting metallization in such a way that at
least the first connecting area of the circuit chip is con-

ected to the connecting metallization in an electrically
conductive manner. The support substrate and the support foil
are then joined in such a way that the connecting metalliza-
tion is connected to the first connecting end of the antenna
5 metallization in an electrically conductive manner and the
second connecting area of the circuit chip is connected to
the second connecting end of the antenna metallization in an
electrically conductive manner. Edge areas of the flexible
support foil are then joined to neighbouring areas of the
10 support substrate so as to encapsulate at least the circuit
chip.

It follows that the present invention provides a method for
producing a microtransponder in the case of which two modules
15 are initially formed, which are joined in the last step. The
first module comprises a support substrate, which may consist
e.g. of plastic material or of paper and on which the antenna
metallization, i.e. the coil, is formed. The second module
comprises a thin support substrate, which consists preferably
20 of plastic material, and which has applied thereto one or
more connecting metallizations and the circuit chip. These
two modules are then joined in such a way that the contacts
required for the electric connections between the coil and
the circuit chip are realized. The support foil is then used
25 for encapsulating the circuit chip and optional further areas
of the coil metallization and of the connecting metalliza-
tions, respectively, by joining edge areas of the support
foil with neighbouring areas of the support substrate by
means of welding or by means of an adhesive so that espe-
30 cially the circuit chip can be protected against external in-
fluences.

According to the present invention, the two modules can first be processed separately from one another so that one module can be processed without taking into consideration the respective other module. The two modules can then be joined in
5 such a way that, when they are being joined, all the necessary electric connections will be established. Through-contacts through the support substrate, which are only required in the case of some embodiments, have to be established in a separate step before or after the joining of the
10 two modules. When the two modules have been joined, the thin support foil, which, on the one hand, serves to handle the circuit chip and the connecting metallization, is used in accordance with the present invention for encapsulating at least the circuit chip and preferably also the areas in which
15 the connections between the connecting metallization and the antenna metallization are realized, by joining edge areas of this thin support foil to the support substrate by means of welding or by means of an adhesive. This encapsulation is carried out preferably in a vacuum or making use of a protective gas so as to prevent an inclusion of possibly detrimental substances.
20

Embodiments and further developments of the present invention are defined in the dependent claims.

25

BRIEF DESCRIPTION OF THE DRAWINGS

In the following, preferred embodiments of the present invention will be explained in detail making reference to the
30 drawings enclosed, in which respective identical elements are designated by identical reference numerals.

Fig. 1a) to 1e) show a schematic representation for illustrating a first embodiment of the method according to the present invention;

5 Fig. 2a) to 2d) show a schematic representation for illustrating a second embodiment of the method according to the present invention;

10 Fig. 3a) to 3e) show a schematic representation for illustrating a third embodiment of the method according to the present invention;

15 Fig. 4a) to 4e) show a schematic representation for illustrating a fourth embodiment of the method according to the present invention;

20 Fig. 5a) to 5e) show a schematic representation for illustrating a fifth embodiment of the method according to the present invention;

Fig. 6a) to 6c) show a schematic representation for illustrating a sixth embodiment of the method according to the present invention;

25 Fig. 7a) to 7c) show a schematic representation for illustrating a seventh embodiment of the method according to the present invention.

30 DESCRIPTION OF PREFERRED EMBODIMENTS OF THE INVENTION

Making reference to Fig. 1, the first embodiment of the method according to the present invention will now be ex-

plained in detail. As has been stated above, two separate modules are first produced in the case of the method for producing a microtransponder according to the present invention. The first module produced is shown in Fig. 1a). In the case of this embodiment, a first connecting metallization 2 and a second connecting metallization 4 are first applied to a thin support foil 6, which consists preferably of plastic material, so as to produce this first module, which can also be referred to as circuit chip module. Subsequently, a circuit chip 8 is applied to the connecting metallizations 2 and 4. The circuit chip 8 comprises the integrated circuit required for the microtransponder and is provided with two connecting areas on or in one main surface thereof; for operating the microtransponder, these connecting areas must be connected to respective connecting ends of a coil antenna metallization. The circuit chip 8 is applied to the connecting metallization 2 in such a way that the first connecting area thereof is connected to the first connecting metallization 2 in an electrically conductive manner, whereas the second connecting area thereof is connected to the connecting metallization 4 in an electrically conductive manner. This results in the structural design of the first module shown in Fig. 1a).

This first module is produced from extremely thin materials. This is important in view of the fact that, when the microtransponder has been finished, the circuit chip 8 with the support foil 6 should not perceptibly project beyond a support substrate on which the coil metallization is arranged. The circuit chip and the foil preferably have a thickness of less than 50 μm .

The connecting metallizations 2 and 4, which may consist e.g. of Al, Cu and the like, can be applied to the foil by arbi-

trary methods, e.g. by cladding and subsequent structuring, by evaporation or sputtering and subsequent structuring, or alternatively by evaporation or sputtering making use of a shadow mask so as to apply lines which are already structured. The connecting metallizations may have a thickness of less than 1 μm , since the conductor tracks of the connecting metallizations can be implemented such that they are short and broad. When the connecting metallizations 2 and 4 have been finished, the circuit chip 8 is placed on the contact areas of the connecting metallizations and is connected thereto in an electrically conductive manner; this can be done e.g. by means of thermocompression, anisotropic conductive adhesives or ultrasonic compression.

In Fig. 1b) the second module is shown, which comprises a support substrate 10 and an antenna metallization 12 applied to a main surface of the support substrate 10. The support substrate may consist e.g. of plastic material or paper. The antenna metallization 12, which has the form of a coil, can again be formed on the support substrate 10 by arbitrary known methods. The coil metallization can e.g. be formed by etching a cladding. Alternatively, a wire can be placed onto the support substrate 10 such that a coil is formed. According to another alternative, a metal, e.g. Cu, Al and the like, can be applied to the support substrate 10 by evaporation and structured subsequently. In order to obtain an adequate thickness of the coil metallization 12 the evaporated metallization can subsequently be thickened by means of an electroplating technique. As can additionally be seen in Fig. 1b), a local thin insulating layer 14 is produced, e.g. by means of a printing process, in an area of the coil metallization 12. This local insulating layer is produced in an area onto which the second connecting metallization 4 will be

placed later on so as to prevent a short circuit between the second connecting metallization 4 and the coil metallization 12.

5 At this point reference should be made to the fact that, alternatively to the application of the insulating layer 14 to the coil metallization 12, this local insulating layer may also be formed on corresponding areas of the first module, e.g. by means of a suitable printing process or by surface
10 oxidation of the metallization. Since the lines of the first module are very thin in comparison with the antenna metallization, which may have a thickness of e.g. 4 to 30 μm , it may be more advantageous to form the insulating layer on the first module, which is shown in Fig. 1a). The insulating
15 layer 14 can consist of an acrylic lacquer having a thickness of 0.2 to 2 μm , this acrylic lacquer being then locally removed at the future contact points; this is done by means of a thermal process. If the local insulating layer is formed on the first module, this can be done prior to or subsequent to
20 the application of the circuit chip 8 to the connecting metallizations 2 and 4.

The first module and the second module are now joined in a subsequent step, as shown in Fig. 1c). In so doing, the first
25 connecting metallization 2 is connected to a first connecting end 16 of the antenna metallization 12 in an electrically conductive manner, whereas the second connecting metallization 4 is connected to a second connecting end 18 of the antenna metallization in an electrically conductive manner. In
30 the embodiment shown in Fig. 1, an isoplanar contact is obtained in this way. As can be seen in Fig. 1d), the support foil 6 is then connected along its edges to the support substrate 10 in such a way that, in the embodiment shown, the

circuit chip 8 as well as the connecting areas between the antenna metallization and the connecting metallization are encapsulated. This can be achieved by bending the edges of the thin support foil 6 towards the support substrate 10 and
5 by subsequently joining the foil areas 20 abutting on the support substrate 10 to the support substrate 10 by means of welding or by means of an adhesive, as can be seen in Fig. 1d). It follows that, according to the present invention, an encapsulation of the circuit chip and, in the case of the em-
10 bodiment shown, of the connection points can be accomplished in a simple manner so as to provide protection against external influences. This connection process between the support foil 6 and the support substrate 10 is preferably carried out in a vacuum.

15 A top view of the microtransponder produced by means of the above method is shown in Fig. 1e). In this top view, especially the shape of the connecting metallizations 2 and 4 and the arrangement of the insulating layer 14 can be seen.

20 Fig. 2 shows a schematic representation of a second embodiment of the production method according to the present invention. The method shown in Fig. 2 corresponds essentially to the method described with reference to Fig. 1, the support
25 substrate 10 having, however, provided therein an opening/recess 30 into which the circuit chip 8 is introduced when the first and second modules are being joined. The opening 30 can be formed in the support substrate 10 by means of arbitrary known methods. Since the support foil 6 and the
30 thin connecting metallization 2 provided thereon are flexible, the shape of the support foil 6 shown at 32 in Fig. 2c) is obtained. One advantage of this embodiment of the method according to the present invention is that the opening 30

permits an improved protection of the circuit chip 8 and that, in addition, the circuit chip can be fixed more effectively. The edge areas of the support foil 6 are again joined to neighbouring areas of the support substrate 10 by means of
5 an adhesive or by means of welding so as to achieve an encapsulation of the circuit chip.

In Fig. 3 a third embodiment of the method according to the present invention is schematically shown. In Fig. 3a) the
10 second module is shown, which corresponds to the above-described second module. In Fig. 3b) the first module is shown, which also corresponds to the above-described first module. Other than in the case of the above-described embodiments, the first and the second module are now, however,
15 joined in such a way that the circuit chip 8 will be positioned on the surface of the support substrate 10 which is located opposite the surface of the support substrate 10 having the antenna metallization 12 formed thereon, cf. Fig. 3c). It follows that in the third embodiment shown, an electrically
20 conductive connection between the first and second connecting ends of the antenna metallization 12 and the first and second connecting metallizations 2 and 4 is not yet established simultaneously with the joining of the first and second modules. In order to realize this electrically conductive
25 connection, through-contacts 40 and 42, respectively, are established, cf. Fig. 3d). By means of the through-contact 42 an electrically conductive connection is established between the first connecting metallization 2 and the first connecting end 16 of the antenna metallization 12,
30 whereas by means of the through-contact 40 an electrically conductive connection is established between the second connecting metallization 4 and the second connecting end 18 of the antenna metallization 12.

In order to establish the through-contacts, thermocompression methods can be used by way of example. Alternatively, the through-contacts can be produced by means of an ultrasonic compression, by means of welding or by means of soldering. In this respect, it should be pointed out that the through-contacts may already be produced when the two modules have not yet been joined, i.e. in the stage of the second module which is shown in Fig. 3a), so that, when the two modules are being joined, the respective electrically conductive connections between the through-contacts and the connecting metallizations will be produced. As can be seen in Fig. 3e), the edge areas 20 of the support foil are again joined to neighbouring areas of the support substrate 10 by means of welding or by means of an adhesive, so as to encapsulate the circuit chip and, in the embodiment shown, additional areas.

The fourth embodiment of the method according to the present invention shown in Fig. 4 differs from the embodiment which has been described with respect to Fig. 3 insofar as the surface of the support substrate 10 located opposite the antenna metallization 12 has formed therein an opening 50 into which the circuit chip 8 is introduced when the first and second modules are being joined. As can be seen in Fig. 4c, this permits an isoplanarity of the connecting metallizations 2 and 4. As in the case of the embodiment according to Fig. 3, through-contacts 40, 42 are again produced for establishing an electrically conductive connection between the connecting metallizations 2 and 4 and the first and second connecting ends 16 and 18 of the antenna metallization 12. Furthermore, also according to the fourth embodiment, the edge areas 20 of the support foil 6 are joined to neighbouring areas of the

support substrate 10 by means of welding or by means of an adhesive so as to effect an encapsulation.

In the case of the method shown in Fig. 5, a circuit chip 60 is used, which is provided with a first connecting area on a first main surface thereof and with a second connecting area on a second main surface thereof. The first module shown in Fig. 5a) is now formed by applying a single connecting metallization 62 to a support foil 6. The circuit chip 60 is applied to the connecting metallization 62, an electrically conductive connection being established between the connecting area of the circuit chip 60 and the connecting metallization 62 e.g. by means of conductive adhesives or by means of soldering.

Fig. 5b) shows the second module; for producing this second module, an antenna metallization 64 is first applied to a support substrate 10. As can be seen in Fig. 5b), the antenna metallization 64 has a preferably enlarged second connecting end 66, the circuit chip 60, whose lower surface may be provided with a metallization 68 thickening the connecting area, being applied to this second connecting end 66 when the first and second modules are being joined. As has already been explained with reference to Fig. 1, a local insulating layer 70 is formed on respective areas of the antenna metallization 64 also in the case of the embodiment shown in Fig. 5 so as to prevent later on a short circuit between the connecting metallization 62 and the antenna metallization 64.

The first module is now connected to the second module, cf. Fig. 5c), a contact between the metallization 68, i.e. the second connecting area on the lower surface of the circuit chip 60, and the second connecting end of the antenna metal-

lization 66 being established simultaneously, and an electrically conductive connection between the connecting metallization 62 and the first connecting end 72 of the antenna metallization 64 being established simultaneously. As can be seen
5 in the detail representations shown in Fig. 5d), the edge areas 20 of the support foil 6 are connected, i.e. joined by means of welding or by means of an adhesive, to corresponding neighbouring areas of the support substrate 10 also in the case of this embodiment. Fig. 5e) shows a top view of the resultant microtransponder.
10

In the sixth embodiment of the method according to the present invention, which is schematically shown in Fig. 6, a first module is again prepared, which essentially corresponds to the first module shown in Fig. 5. This first module
15 is shown in Fig. 6b). The second module differs from the module described with reference to Fig. 5 insofar as an opening 80 is formed in the main surface of the support substrate 10 facing away from the antenna metallization 64, Fig. 6a). As
20 can be seen in Fig. 6c), the circuit chip 60 is introduced in this opening 80 when the two modules according to this embodiment are being joined. For establishing an electric contact between the connecting area, or the reinforcement 68, arranged on the upper surface of the circuit chip and the
25 second connecting end 66 of the antenna metallization 64, it is necessary to eliminate, preferably by means of a thermally supported method, the web 82 of the support substrate arranged above the opening 80, so as to establish an electrically conductive connection between the connecting area arranged on the upper surface of the circuit chip 60 and the
30 second connecting end 66 of the antenna metallization 64. Furthermore, a through-contact 84 is produced so as to establish an electrically conductive connection between the con-

necting metallization 62 and the first connecting end 72 of
the antenna metallization 64. Also in the case of this em-
bodiment, the edges of the support foil 6 are joined to the
support substrate 10 by means of welding or by means of an
5 adhesive so as to obtain an encapsulation.

Also in the embodiment which is schematically shown in Fig.
7, a circuit chip 60 with double-sided contacting is used.
Other than in the case of the method described with reference
10 to Fig. 6, the support substrate 10 has now provided therein
an opening 90 which extends through the whole support sub-
strate 10 up to the second connecting end 66 of the coil met-
tallization 64. The rest of the method for producing the mi-
crotransponder according to the embodiment shown in Fig. 7
15 corresponds essentially to the method which has been de-
scribed with reference to Fig. 6, but the heat treatment for
eliminating a web above the opening 90 can now be dispensed
with, since such a web does not exist. The other steps corre-
spond to the steps which have been described with reference
20 to Fig. 6.

It should be pointed out that the second connecting end 66 of
the antenna metallization 64 may cover the circuit chip 60
completely or partially. Furthermore, the metallization 68 on
25 the circuit chip 60 may cover the circuit chip completely or
partially; a person skilled in the art will also be aware of
the fact that, with the exception of the connecting area of
the circuit chip 60, a passivation layer is arranged between
the metallization 68 and the circuit chip 60.

30

It follows that the present invention provides a simple tech-
nique for producing a microtransponder in the case of which
the production of the antenna module and the production of

the circuit chip module are completely separated. The circuit chip module can be implemented such that it is much thinner than the antenna module. Various production techniques can be used for producing the antenna module and for producing the
5 circuit chip module. Due to the fact that the circuit chip is encapsulated or that large areas thereof are covered by a metallization, good light protection can be achieved. The methods according to the present invention are preferably executed such that the individual modules are formed on an
10 endless material and are then sequentially supplied to a processing station in which the modules are joined. The respective metallic layers may consist of a ferromagnetic material so as to permit, if necessary, magnetic handling of the individual modules or of the finished microtransponder. For
15 handling the thin circuit chip module, the circuit chip module may be supported by an additional support so as to stabilize it, whereby distortions or even rolling up due to internal mechanical stress can be avoided. The encapsulation of the circuit chip and of additional optional areas is preferably
20 bly carried out in a vacuum or while a protective gas, e.g. a forming gas, is being supplied.

Claims

What is claimed is:

- 5 1. A method for producing a microtransponder comprising the following steps:

applying an antenna metallization ~~(12; 64)~~ having a first
~~(16; 72)~~ and a second ~~(18; 66)~~ connecting end to a support
10 substrate ~~(10)~~;

applying a connecting metallization ~~(2, 4; 62)~~ to a flexi-
ble support foil ~~(6)~~;

- 15 a) applying a circuit chip ~~(8; 60)~~ having a first and a
second connecting area to said connecting metallization
~~(2, 4; 62)~~ in such a way that at least the first con-
necting area of the circuit chip is connected to the
connecting metallization ~~(2; 62)~~ in an electrically
20 conductive manner;

- b) joining the support substrate ~~(10)~~ and the support foil
~~(6)~~ in such a way that the connecting metallization ~~(2;~~
~~62)~~ is connected to the first connecting end ~~(16; 72)~~
25 of the antenna metallization ~~(12; 64)~~ in an electri-
cally conductive manner, and that the second connecting
area of the circuit chip ~~(8; 60)~~ is connected to the
second connecting end ~~(18; 66)~~ of the antenna metalli-
zation ~~(12; 64)~~ in an electrically conductive manner;
30 and

c) joining edge areas~~-(20)~~ of the flexible support foil~~-(6)~~ to neighbouring areas of the support substrate~~-(10)~~ so as to encapsulate at least the circuit chip~~-(8; 60)~~.

5 2. A method according to claim 1, wherein the edge areas~~-(20)~~ of the flexible support foil~~-(6)~~ are welded to the neighbouring areas of the support substrate~~-(10)~~.

10 3. A method according to claim 1, wherein the edge areas~~-(20)~~ of the flexible support foil~~-(6)~~ are joined to the neighbouring areas of the support substrate~~-(10)~~ by means of an adhesive.

15 4. A method according to ~~one of the claims 1 to 3~~, wherein in step b) a first and a second connecting metallization~~-(2, 4)~~ are applied to the flexible support foil~~-(6)~~, and wherein in step c) the circuit chip~~-(8)~~, which is provided with said first and second connecting areas on a first main surface thereof, is applied to said first and
20 said second connecting metallizations~~-(2, 4)~~ in such a way that the first connecting area is connected to the first connecting metallization~~-(2)~~ in an electrically conductive manner and the second connecting area is connected to the second connecting metallization~~-(4)~~ in an
25 electrically conductive manner, the second connecting area being, in step d), connected via the second connecting metallization~~-(4)~~ to the second connecting end~~-(18)~~ of the antenna metallization~~-(12)~~ in electrically conductive manner.

30

5. A method according to ~~one of the claims 1 to 3~~, wherein the circuit chip~~-(60)~~ applied in step c) has the first connecting area on a first main surface thereof and the

second connecting area on a second main surface thereof,
which is located opposite said first main surface.

6. A method according to claim 4, wherein in step d) the
5 support foil ~~(6)~~ and the support substrate ~~(10)~~ are
joined in such a way that the antenna metallization ~~(12)~~
and the circuit chip ~~(8)~~ are arranged on the same main
surface of the support substrate ~~(10)~~.
- 10 7. A method according to claim 4, wherein the circuit chip
~~(8)~~ is introduced in step d) in an opening ~~(30)~~ in the
support-substrate main surface to which the antenna met-
allization ~~(12)~~ has been applied.
- 15 8. A method according to claim ~~6~~ or ~~7~~, wherein an insulator
structure ~~(14)~~ is provided so as to insulate the second
connecting metallization ~~(4)~~ from the antenna metalliza-
tion ~~(12)~~ with the exception of the location at the sec-
ond connecting end ~~(18)~~ of the antenna metallization
20 ~~(12)~~.
9. A method according to claim 4, wherein the support foil
~~(6)~~ and the support substrate ~~(10)~~ are joined in step d)
in such a way that the antenna metallization ~~(12)~~ and the
25 circuit chip ~~(8)~~ are arranged on opposed main surfaces of
the support substrate ~~(10)~~, the first and second connect-
ing metallizations ~~(2, 4)~~ being connected by means of
through-contacts ~~(40, 42)~~ to the first and second con-
necting ends ~~(16, 18)~~ of the antenna metallization ~~(12)~~.
- 30 10. A method according to claim 4, wherein in step d) the
circuit chip ~~(8)~~ is introduced in an opening ~~(50)~~ pro-
vided in the main surface of the support substrate ~~(10)~~

which is located opposite the main surface having the antenna metallization~~-(12)~~ applied thereto, the first and second connecting metallizations~~-(2, 4)~~ being connected by means of through-contacts~~-(40, 42)~~ to the first and second connecting ends~~-(16, 18)~~ of the antenna metallization~~-(12)~~.

11. A method according to claim 5, wherein the support foil ~~(6)~~ and the support substrate~~-(10)~~ are joined in step d) in such a way that the antenna metallization~~-(64)~~ and the circuit chip~~-(60)~~ are arranged on the same main surface of the support substrate~~-(10)~~.

12. A method according to claim 5, wherein in step d) the circuit chip~~-(60)~~ is introduced into an opening~~-(80, 90)~~ provided in the main surface of the support substrate ~~(10)~~ which is located opposite the main surface having the antenna metallization~~-(64)~~ applied thereto, the connecting metallization~~-(62)~~ being connected via a through-contact~~-(84)~~ to the first connecting end~~-(72)~~ of the antenna metallization~~-(64)~~.

13. A method according to ~~one of the claims 1 to 12~~, wherein step e) is executed in a vacuum or making use of a protective gas.

~~Method for Producing a Microtransponder~~

ABSTRACT

5 According to a method for producing a microtransponder, an antenna metallization~~-(12)~~ having a first~~-(16)~~ and a second~~-(18)~~ connecting end is first applied to a support substrate~~-(10)~~ so as to form a first module. A connecting metallization~~-(2, 4)~~ is applied to a flexible support foil~~-(6)~~, whereupon a
10 circuit chip~~-(8)~~ having a first and a second connecting area is applied to said connecting metallization~~-(2, 4)~~ in such a way that at least the first connecting area of the circuit chip~~-(8)~~ is connected to said connecting metallization~~-(2, 4)~~ in an electrically conductive manner. The flexible support
15 foil~~-(6)~~ having the circuit chip~~-(8)~~ applied thereto represents a second module. The first and the second module are subsequently joined in such a way that the connecting metallization~~-(2, 4)~~ is connected to the first connecting end of the antenna metallization~~-(12)~~ in an electrically conductive
20 manner and the second connecting area of the circuit chip~~-(8)~~ is connected to the second connecting end of the antenna metallization~~-(12)~~ in an electrically conductive manner. Finally, edge areas of the flexible support foil~~-(6)~~ are joined to neighbouring areas of the support substrate~~-(10)~~ so as to
25 encapsulate at least the circuit chip~~-(8)~~.

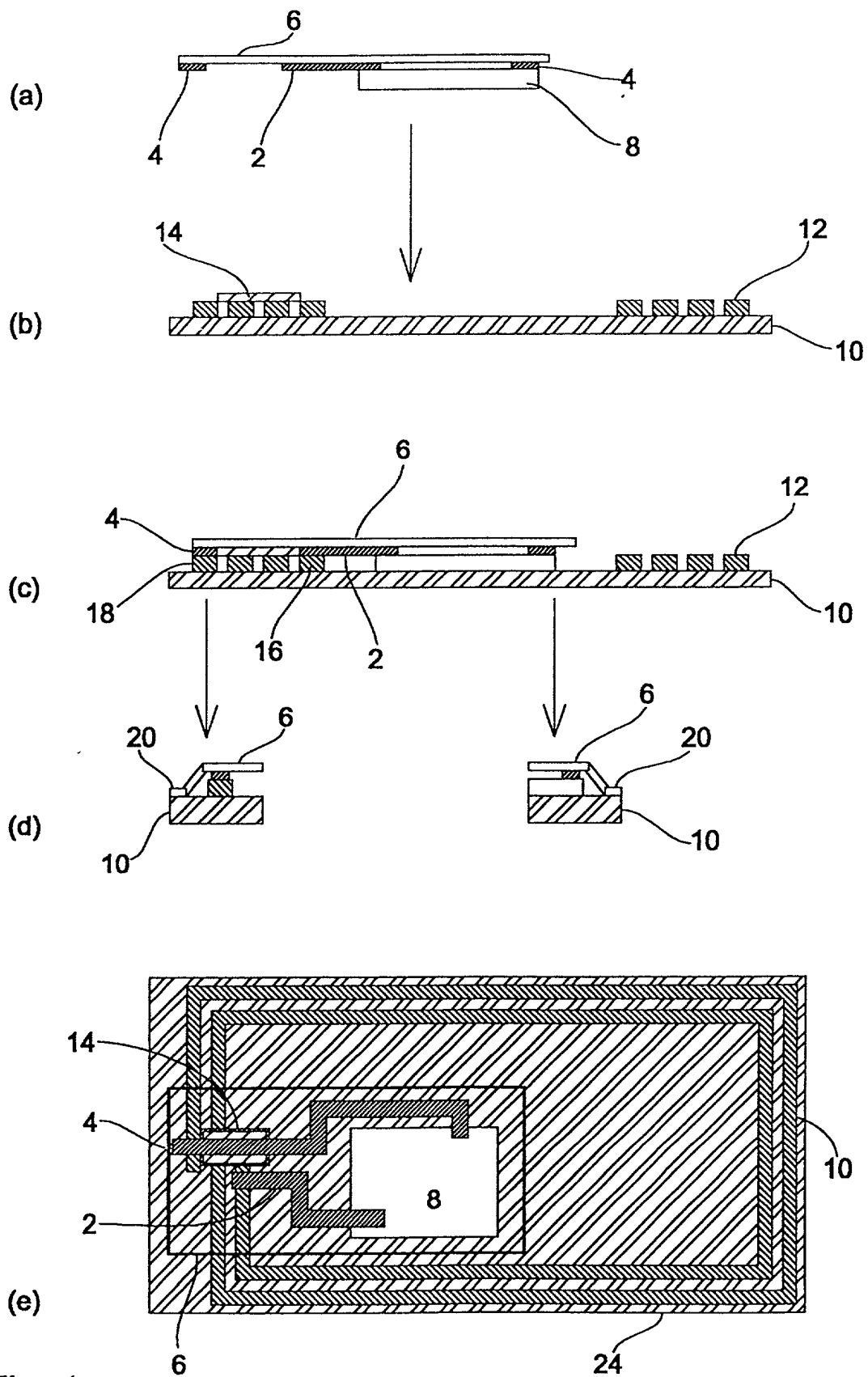


Fig. 1

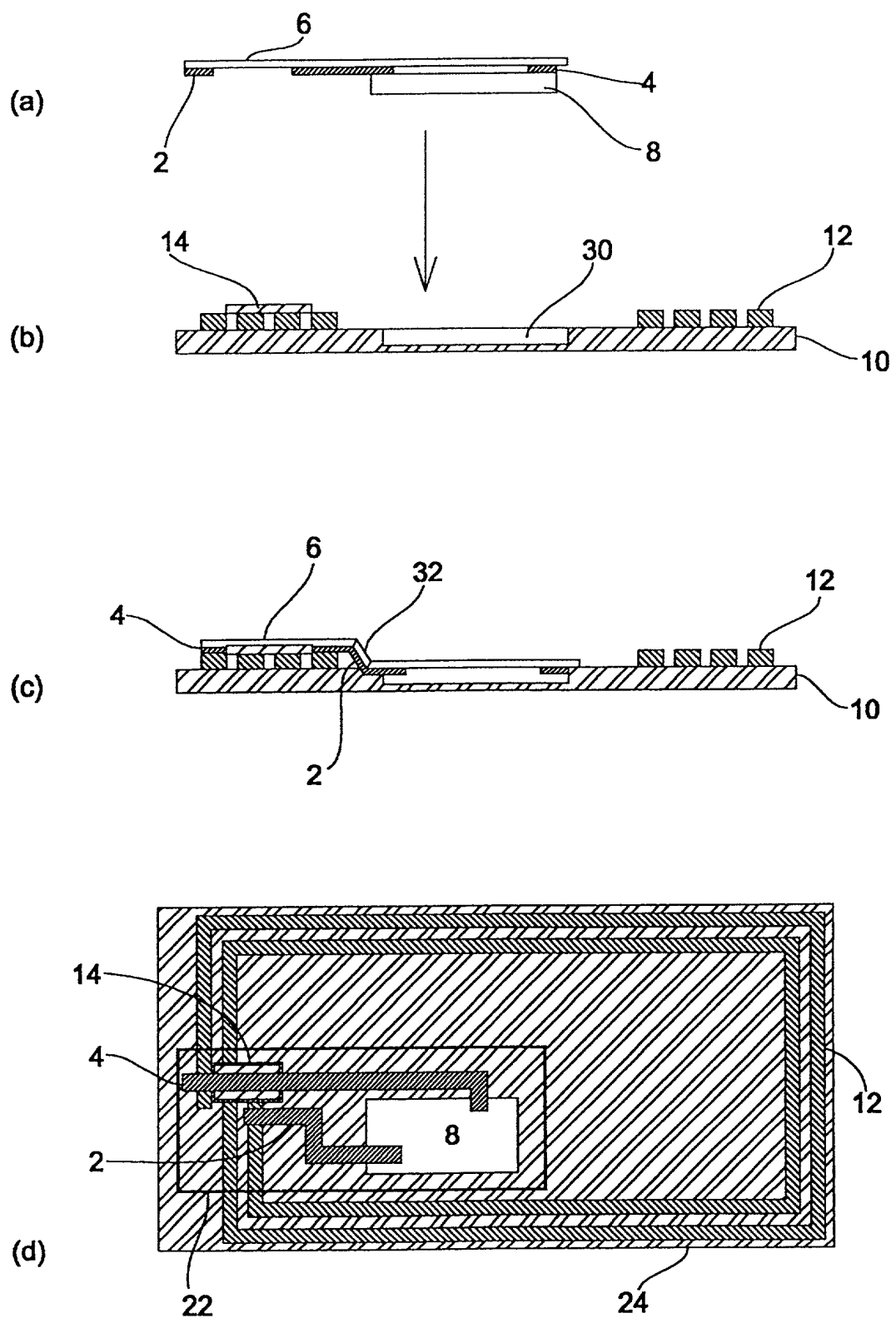


Fig. 2

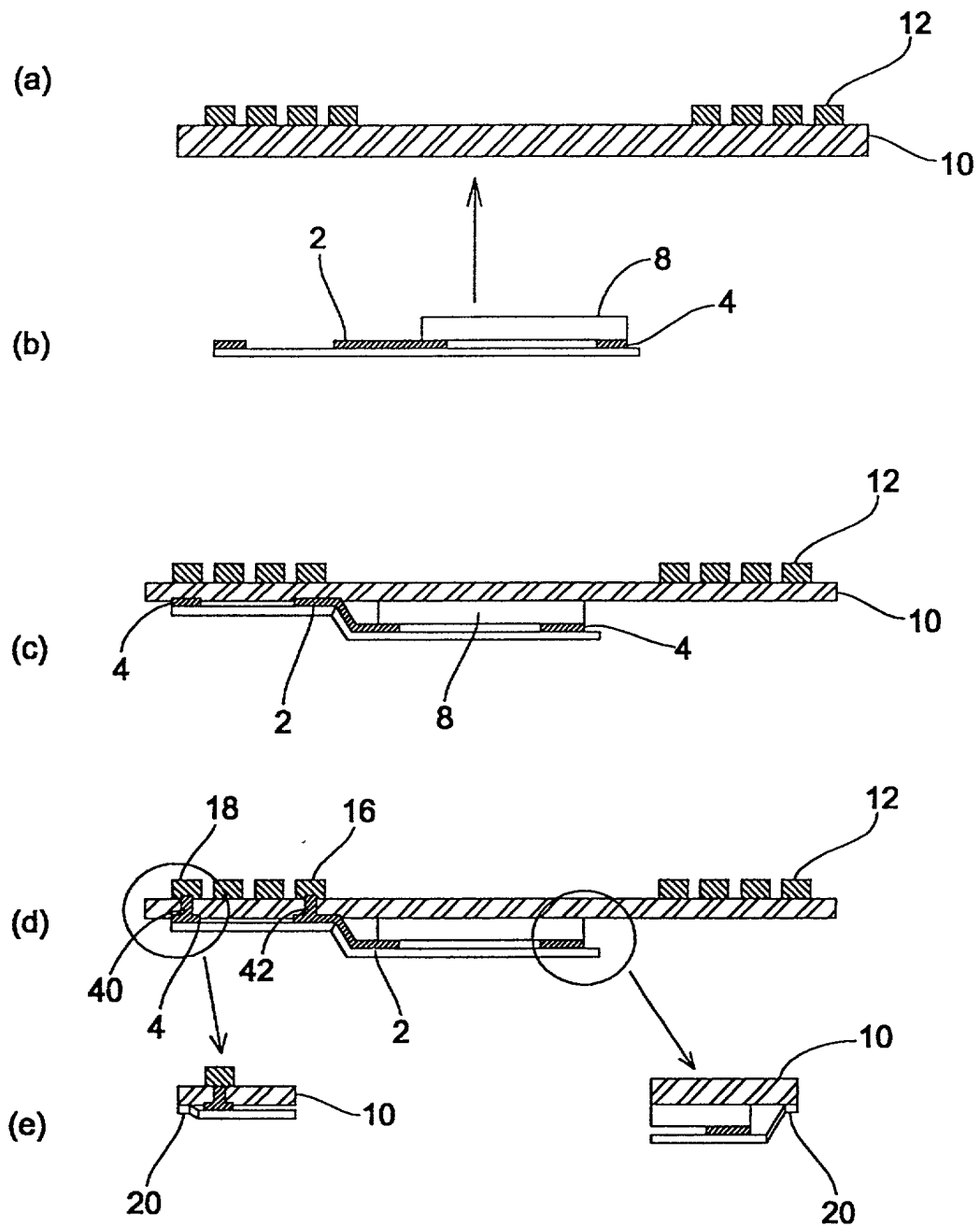


Fig. 3

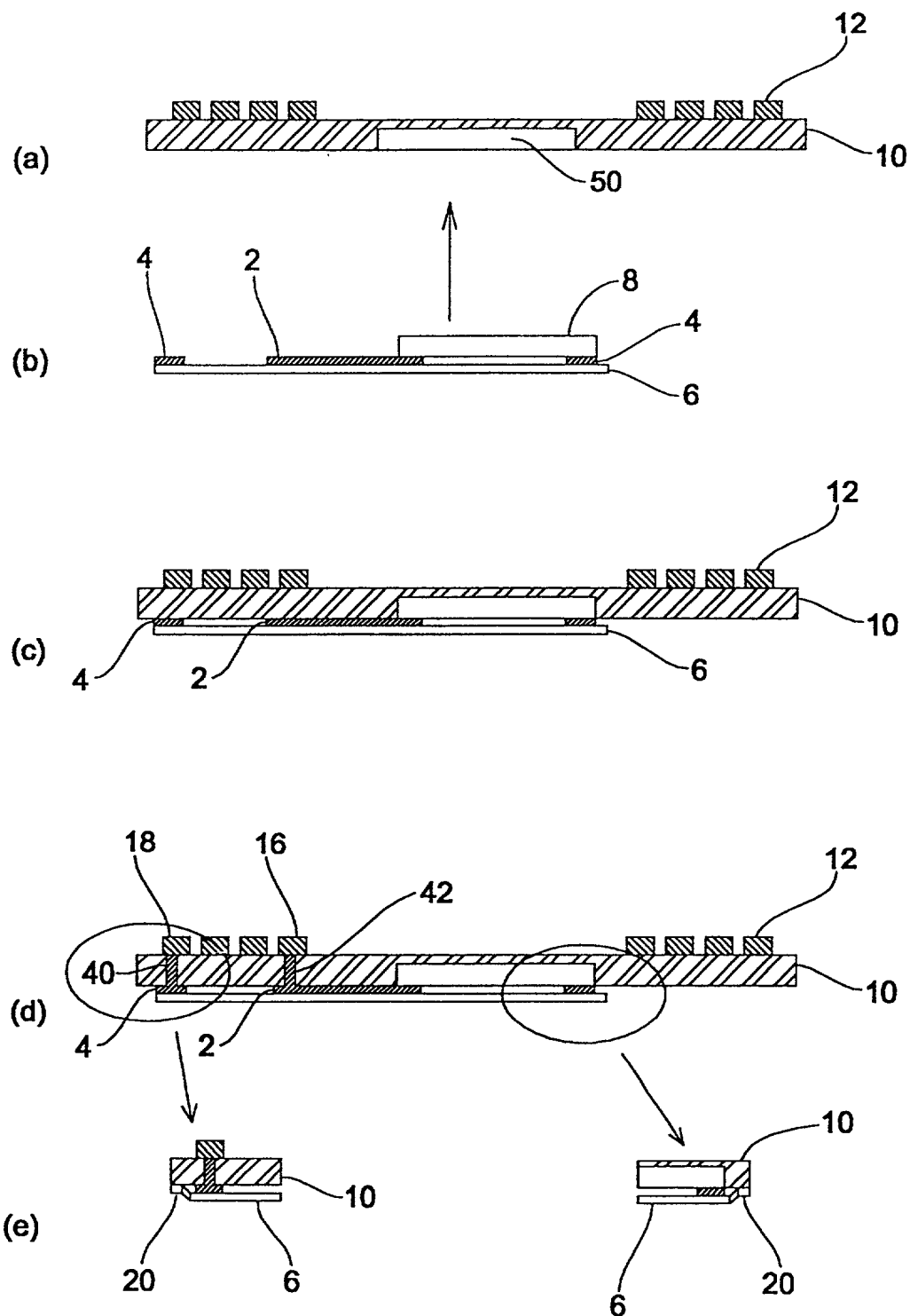
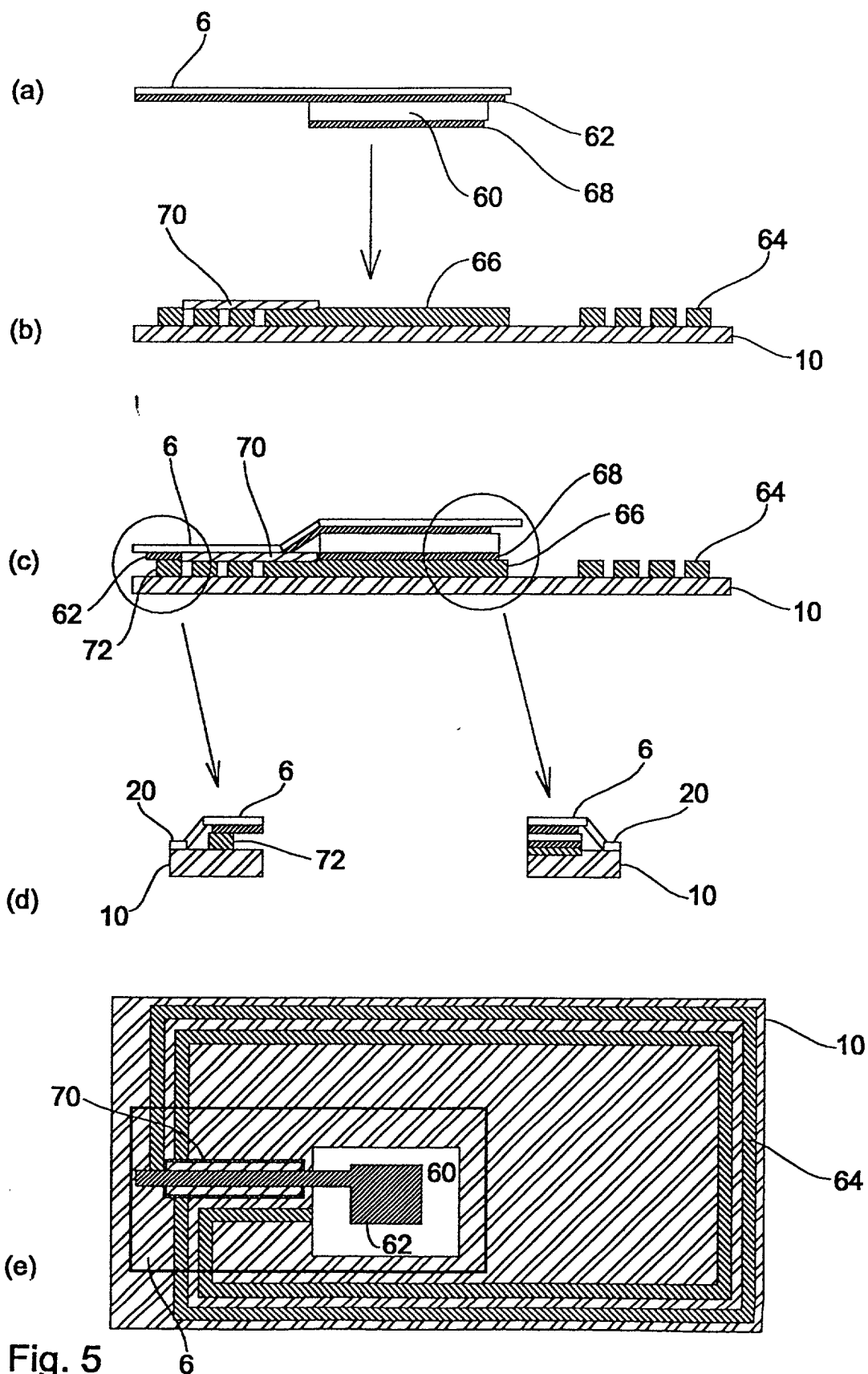


Fig. 4



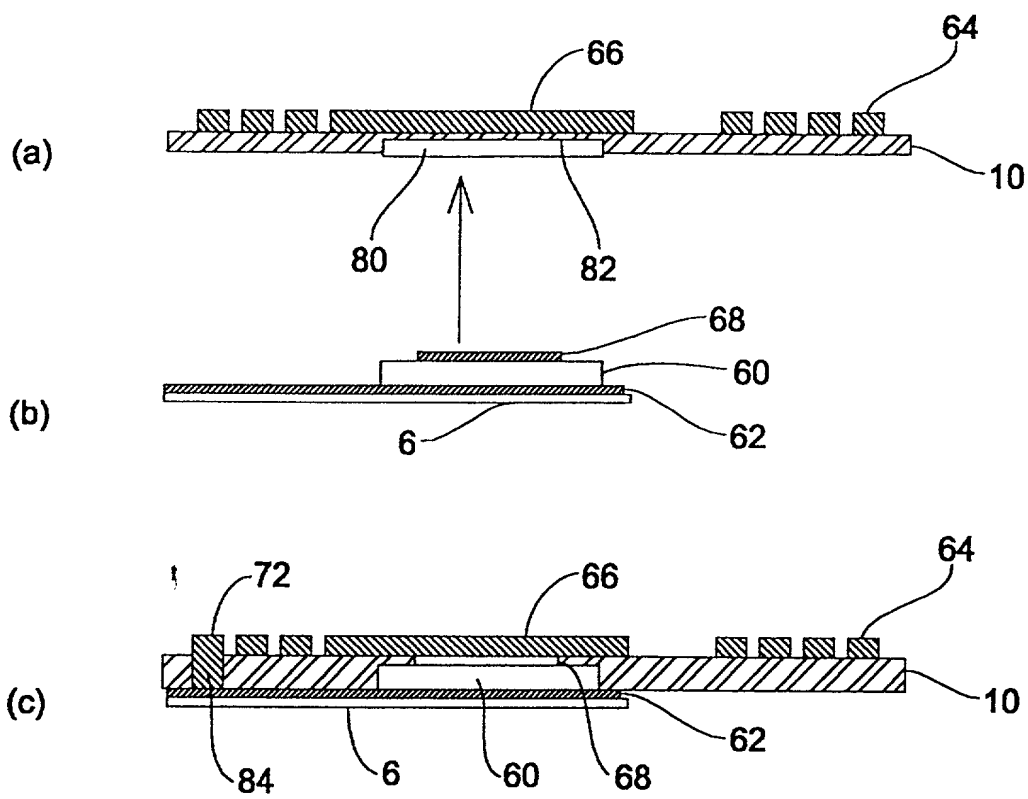


Fig. 6

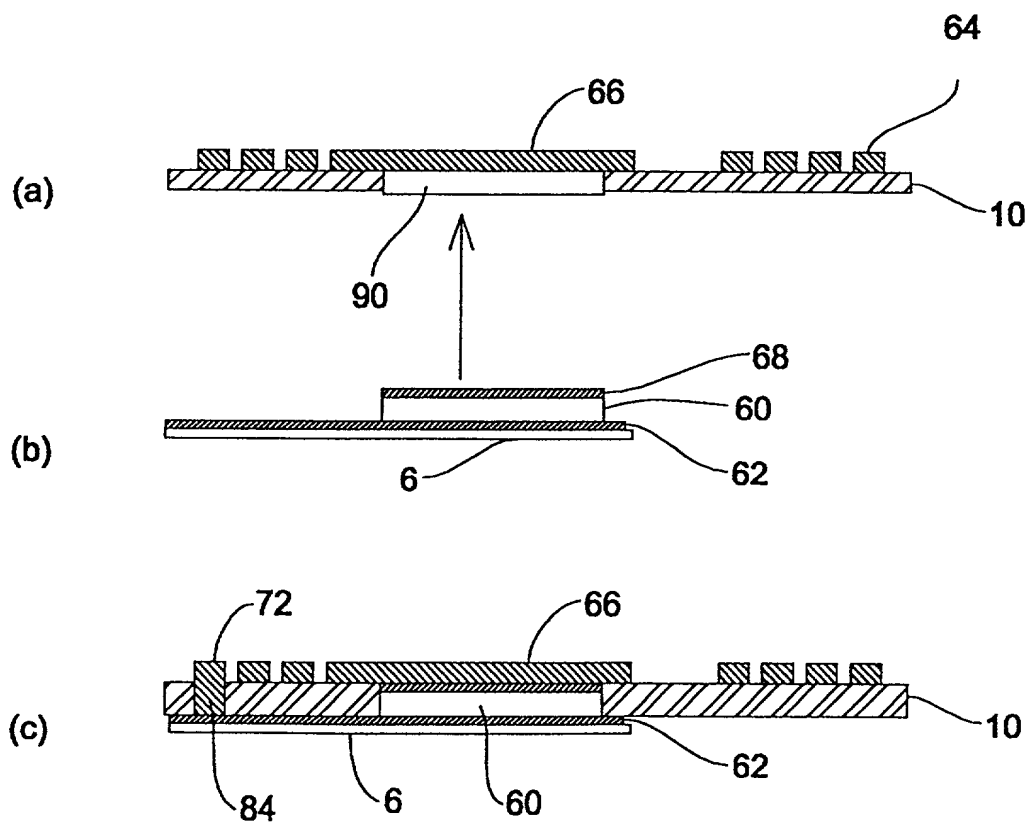


Fig. 7

Declaration and Power of Attorney for Patent Application Erklärung für Patentanmeldungen mit Vollmacht



German Language Declaration

Als nachstehend benannter Erfinder erkläre ich hiermit an Eides Statt:

daß mein Wohnsitz, meine Postanschrift und meine Staatsangehörigkeit den im nachstehenden nach meinem Namen aufgeführten Angaben entsprechen, daß ich nach bestem Wissen der ursprüngliche, erste und alleinige Erfinder (falls nachstehend nur ein Name angegeben ist) oder ein ursprünglicher, erster und Miterfinder (falls nachstehend mehrere Namen aufgeführt sind) des Gegenstandes bin, für den dieser Antrag gestellt wird und für den ein Patent für die Erfindung mit folgendem Titel beantragt wird:

deren Beschreibung hier beigelegt ist, es sei denn (in diesem Falle Zutreffendes bitte ankreuzen), diese Erfindung

- ☐ wurde angemeldet am _____
unter der US-Anmeldenummer oder unter der
Internationalen Anmeldenummer im Rahmen des
Vertrags über die Zusammenarbeit auf dem Gebiet
des Patentwesens (PCT)
_____ und am
_____ abgeändert (falls
zutreffend).

Ich bestätige hiermit, daß ich den Inhalt der oben angegebenen Patentanmeldung, einschließlich der Ansprüche, die eventuell durch einen oben erwähnten Zusatzantrag abgeändert wurde, durchgesehen und verstanden habe.

Ich erkenne meine Pflicht zur Offenbarung jeglicher Informationen an, die zur Prüfung der Patentfähigkeit in Einklang mit Titel 37, Code of Federal Regulations, § 1.56 von Belang sind.

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

METHOD FOR PRODUCING A MICROTRANSPONDER

the specification of which is attached hereto unless the following box is checked:

- ☒ was filed on March 20, 2001
as United States Application Number or PCT
International Application Number
09/787,638 and was amended on
_____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

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Prior Foreign Applications
(Frühere ausländische Anmeldungen)

PCT/EP99/07534	Germany
(Number)	(Country)
(Nummer)	(Land)
19846237.9	Germany
(Number)	(Country)
(Nummer)	(Land)

Ich beanspruche hiermit Prioritätsvorteile unter Title 35, US-Code, § 119(e) aller US-Hilfsanmeldungen wie unten aufgezählt.

(Application No.)	(Filing Date)
(Antragsnummer)	(Anmeldetag)

(Application No.)	(Filing Date)
(Antragsnummer)	(Anmeldetag)

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(Antragsnummer)	(Anmeldetag)

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(Antragsnummer)	(Anmeldetag)

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Priority Not Claimed
Priorität nicht beansprucht

07/10/99 (October 7, 1999)
(Day/Month/Year Filed)
(Tag/Monat/Jahr der Anmeldung)
07/10/98 (October 7, 1998)
(Day/Month/Year Filed)
(Tag/Monat/Jahr der Anmeldung)

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below.

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(Status) (patented, pending, abandoned)
(Status) (patentiert, schwebend, aufgegeben)

(Status) (patented, pending, abandoned)
(Status) (patentiert, schwebend, aufgegeben)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: (list name and registration number)

Ralph H. Dougherty - Reg. No. 25,851
 Gregory N. Clements - Reg. No. 30,713
 J. Scott Young - Reg. No. 45,582
 David P. Stitzel - Reg. No. 44,360

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Ralph H. Dougherty (704) 366-6642

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Unterschrift des Erfinders	Inventor's signature
Datum	Date
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Staatsangehörigkeit	Citizenship
	German
Postanschrift	Post Office Address
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Vor- und Zuname des zweiten Miterfinders (falls zutreffend)	Full name of second joint inventor, if any
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Unterschrift des zweiten Erfinders	Second Inventor's signature
Datum	Date
Wohnsitz	Residence
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Staatsangehörigkeit	Citizenship
	German
Postanschrift	Post Office Address
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(Im Falle dritter und weiterer Miterfinder sind die entsprechenden Informationen und Unterschriften hinzuzufügen.)

(Supply similar information and signature for third and subsequent joint inventors.)

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POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: (list name and registration number)

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Vor- und Zuname des einzigen oder ersten Erfinders	Full name of sole or first inventor	Andreas PLETTNER
Unterschrift des Erfinders	Inventor's signature	
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Postanschrift	Post Office Address	Lennestrasse 5
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Vor- und Zuname des zweiten Miterfinders (falls zutreffend)	Full name of second joint inventor, if any	Karl HABERGER
Unterschrift des zweiten Erfinders	Second Inventor's signature	
Datum	Date	April 6, 2001
Wohnsitz	Residence	Martinsried, Germany DEX
Staatsangehörigkeit	Citizenship	German
Postanschrift	Post Office Address	Lena-Christ-Straße 34b
		D-82152 Martinsried, Germany

(Im Falle dritter und weiterer Miterfinder sind die entsprechenden Informationen und Unterschriften hinzuzufügen.)

(Supply similar information and signature for third and subsequent joint inventors.)